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(54) **CHIP RESISTOR AND METHOD FOR MAKING THE SAME**

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CPC ***H01C 1/14*** (2013.01); ***H01C 17/006*** (2013.01); ***H01C 17/06*** (2013.01); *Y10T 29/49082* (2015.01); ***H01C 17/283*** (2013.01)

(57) **ABSTRACT**

A chip resistor includes first and second electrodes spaced apart from each other, a resistor element arranged on the first and the second electrodes, a bonding layer provided between the resistor element and the two electrodes, and a plating layer electrically connected to the resistor element. The first electrode includes a flat outer side surface, and the resistor element includes a side surface facing in the direction in which the thirst and the second electrodes are spaced. The outer side surface of the first electrode is flush with the side surface of the resistor element. The plating layer covers at least a part of the outer side surface of the first electrode in a manner such that the covering portion of the plating layer extends from one vertical edge of the outer side surface to the other vertical edge.

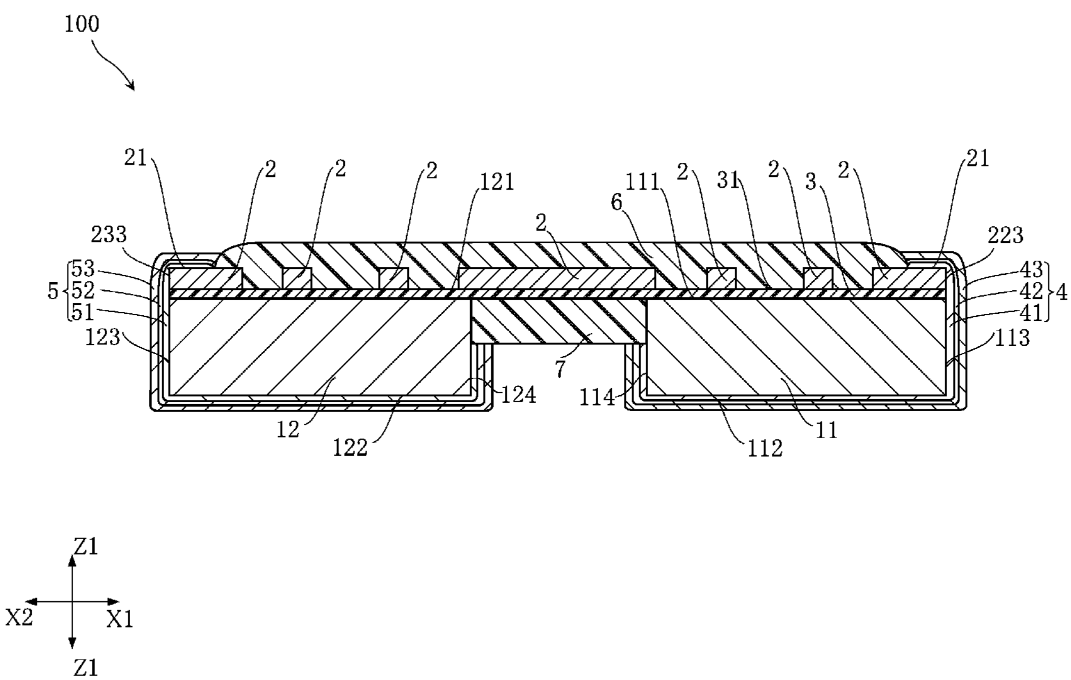
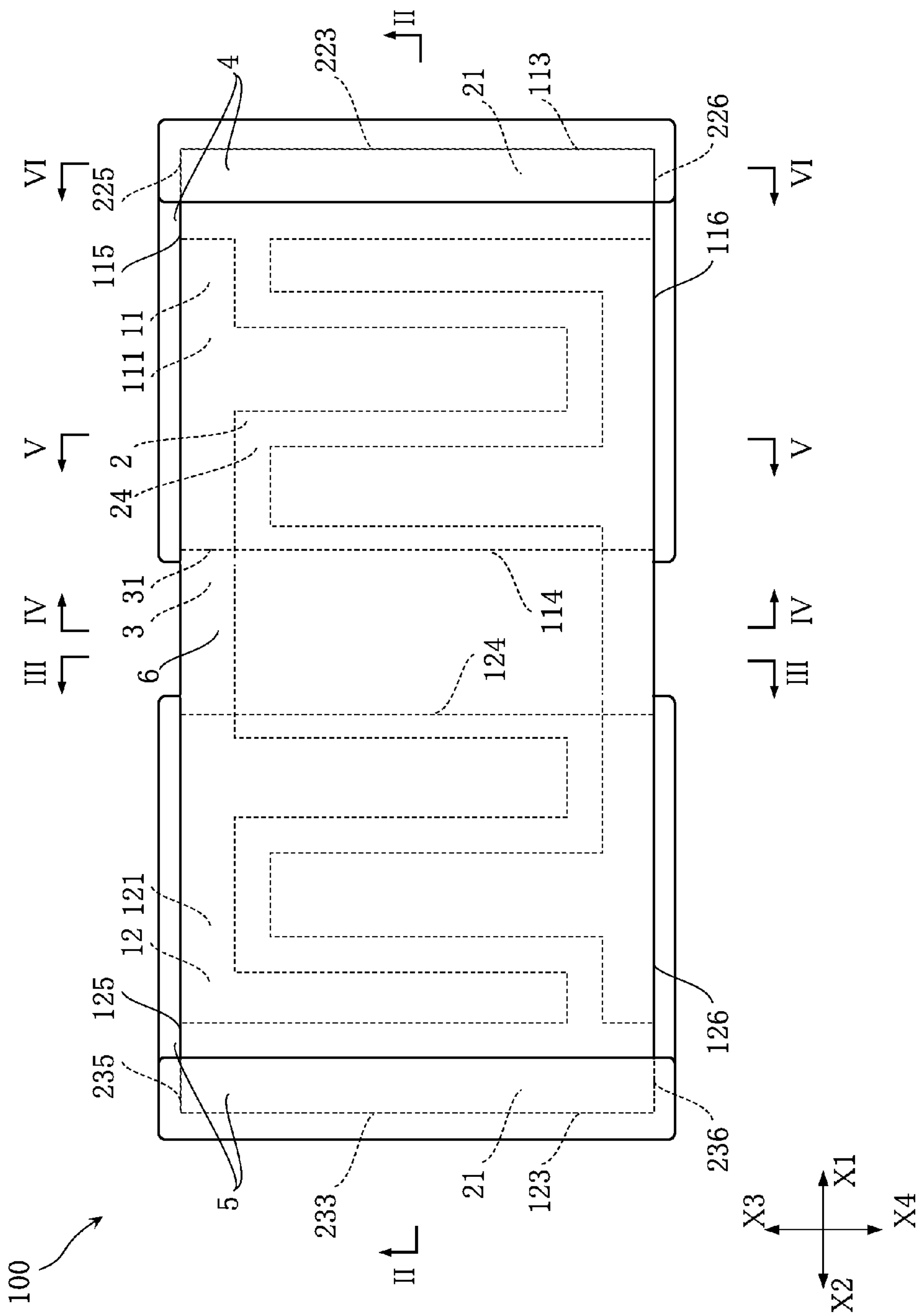


FIG.1



100
II
II
III
III
IV
IV
V
V
VI
VI
4
5
223
21
113
226
225
115
116
11
111
2
24
31
3
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235
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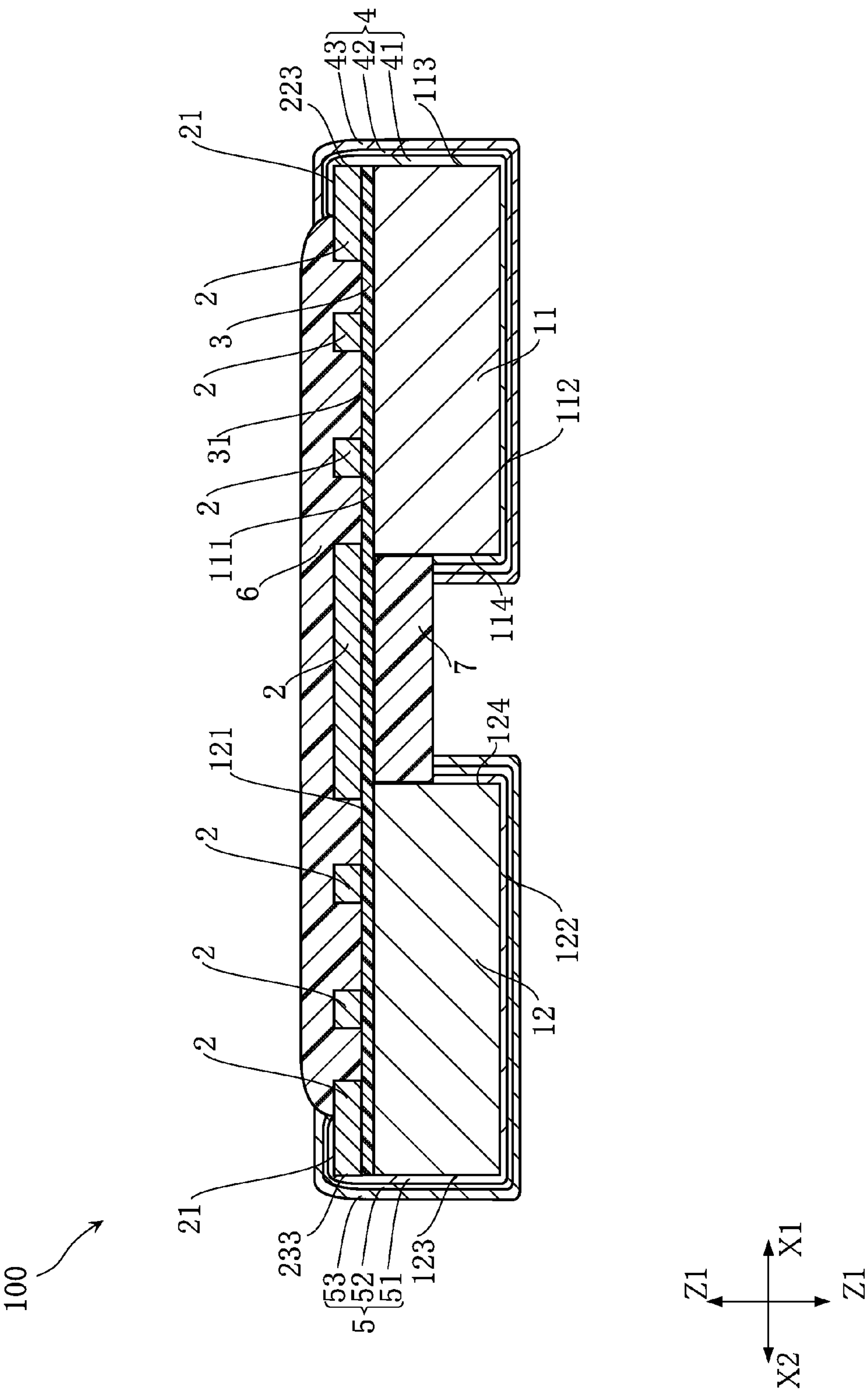
123
236
X1
X2
X3
X4

FIG.2



100
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6
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112
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7
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53
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51
5
123
X1
X2
Z1
Z1

FIG.3

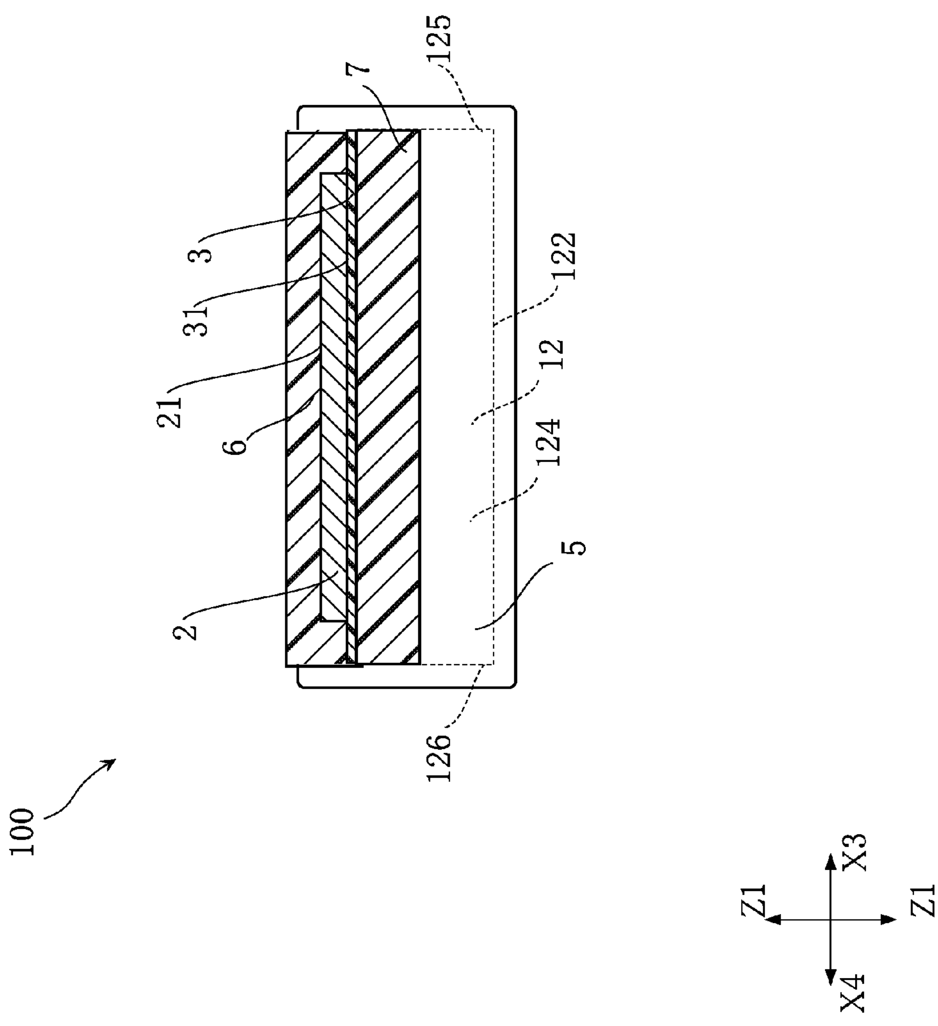


FIG.4

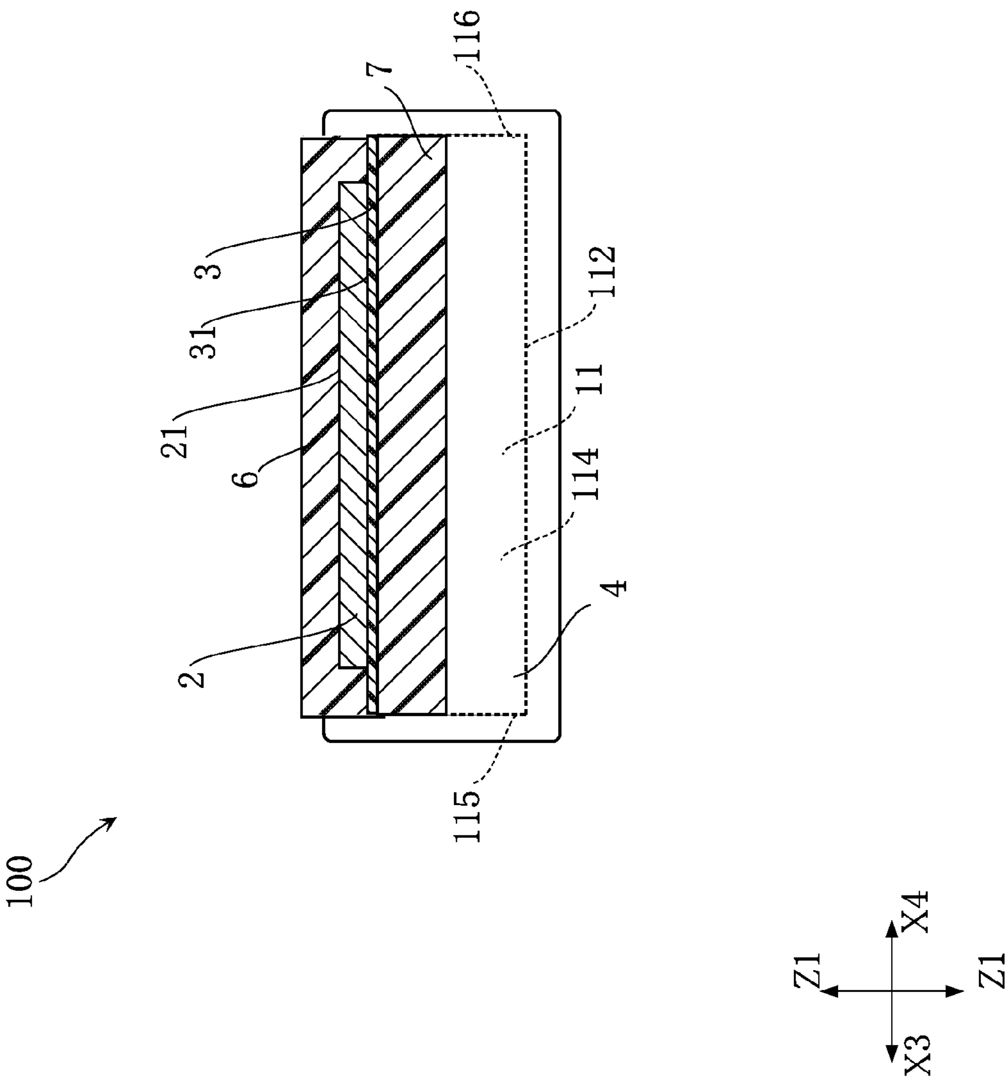


FIG.5

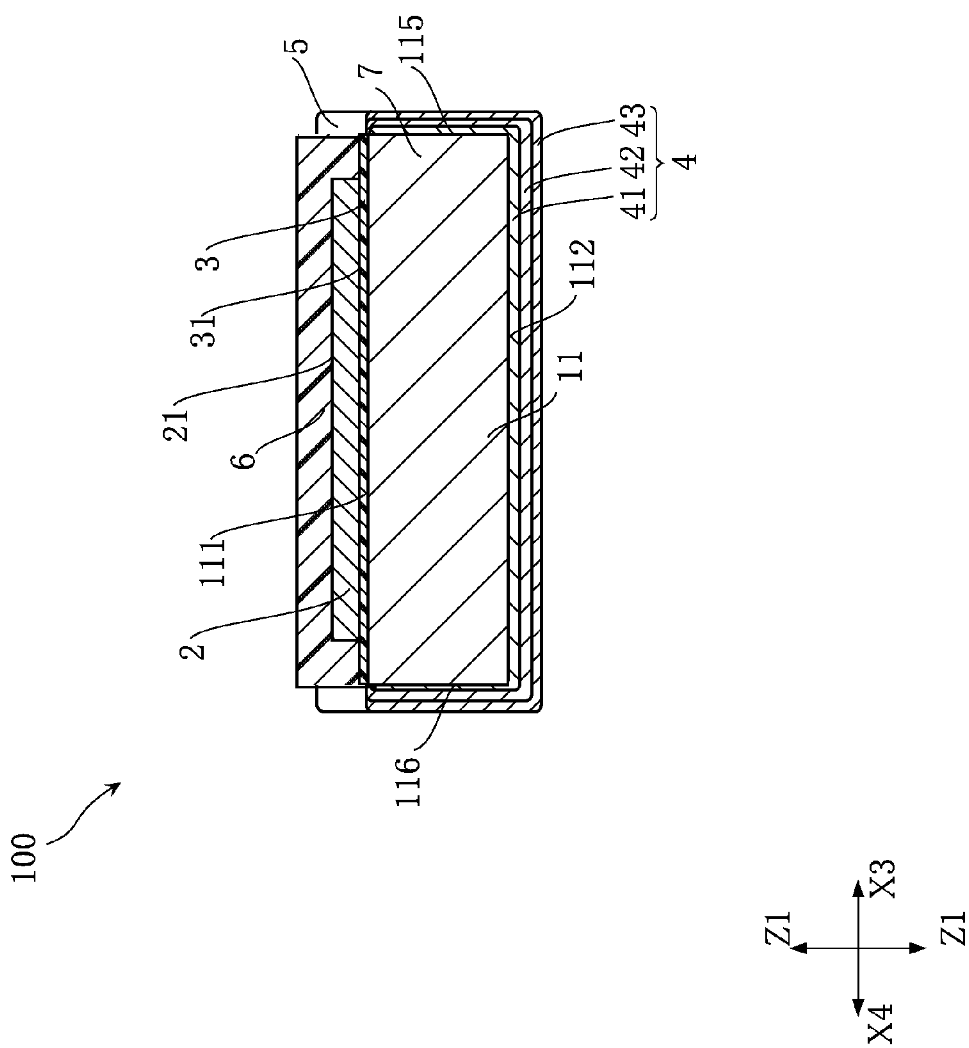


FIG.6

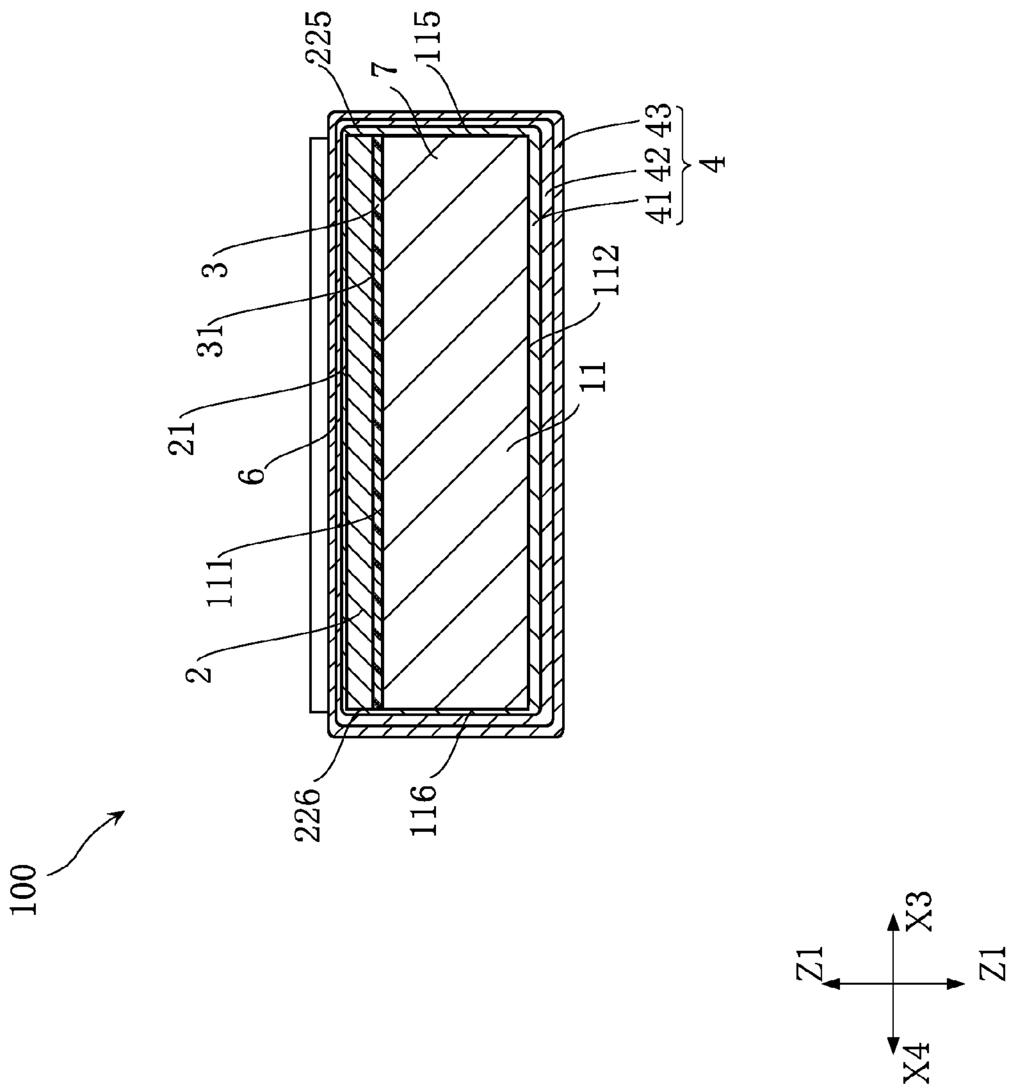


FIG.7

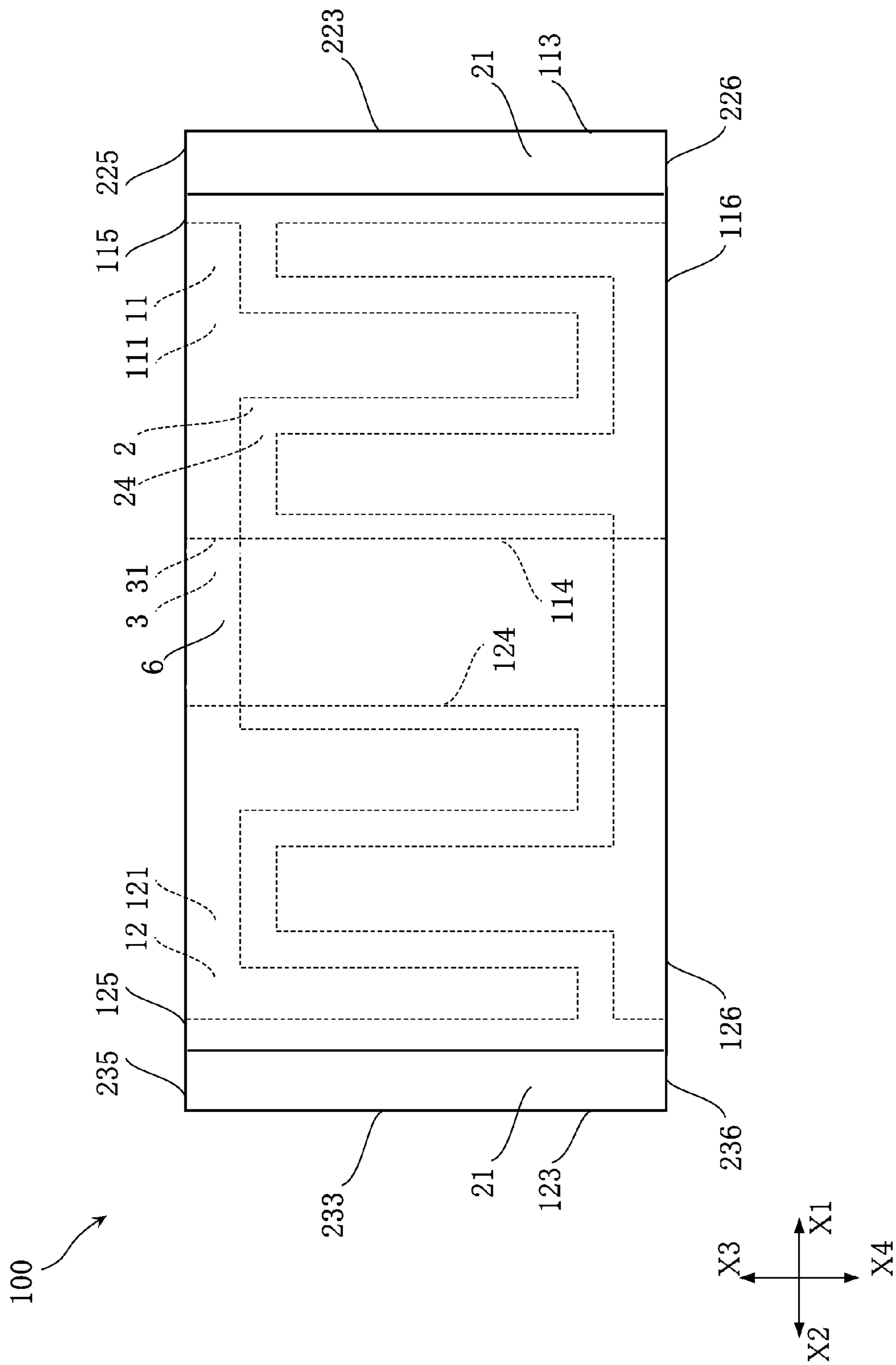

223
21
113
226
225
115
116
111 11
24 2
3 31
6
114
124
12 121
125
126
235
236
233
21
123
100
X1
X2
X3
X4

FIG.8

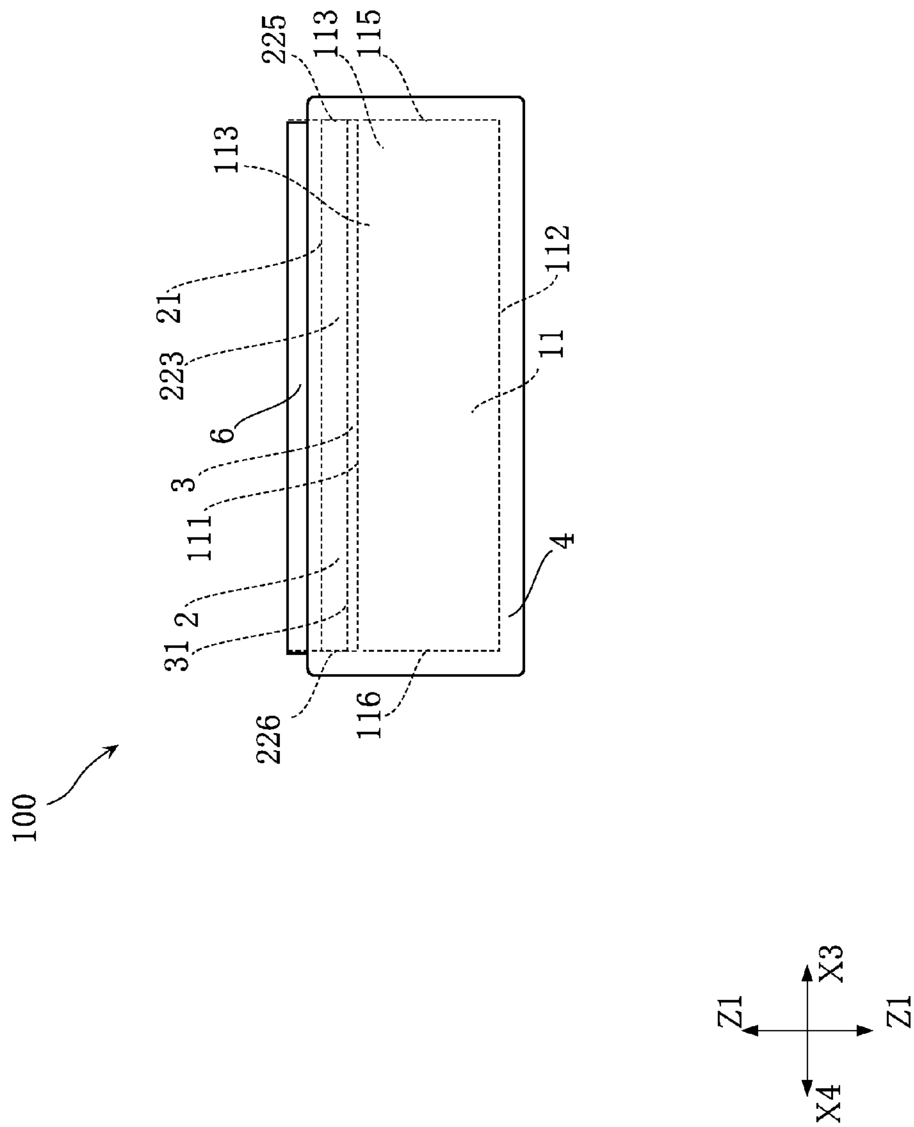


FIG.9

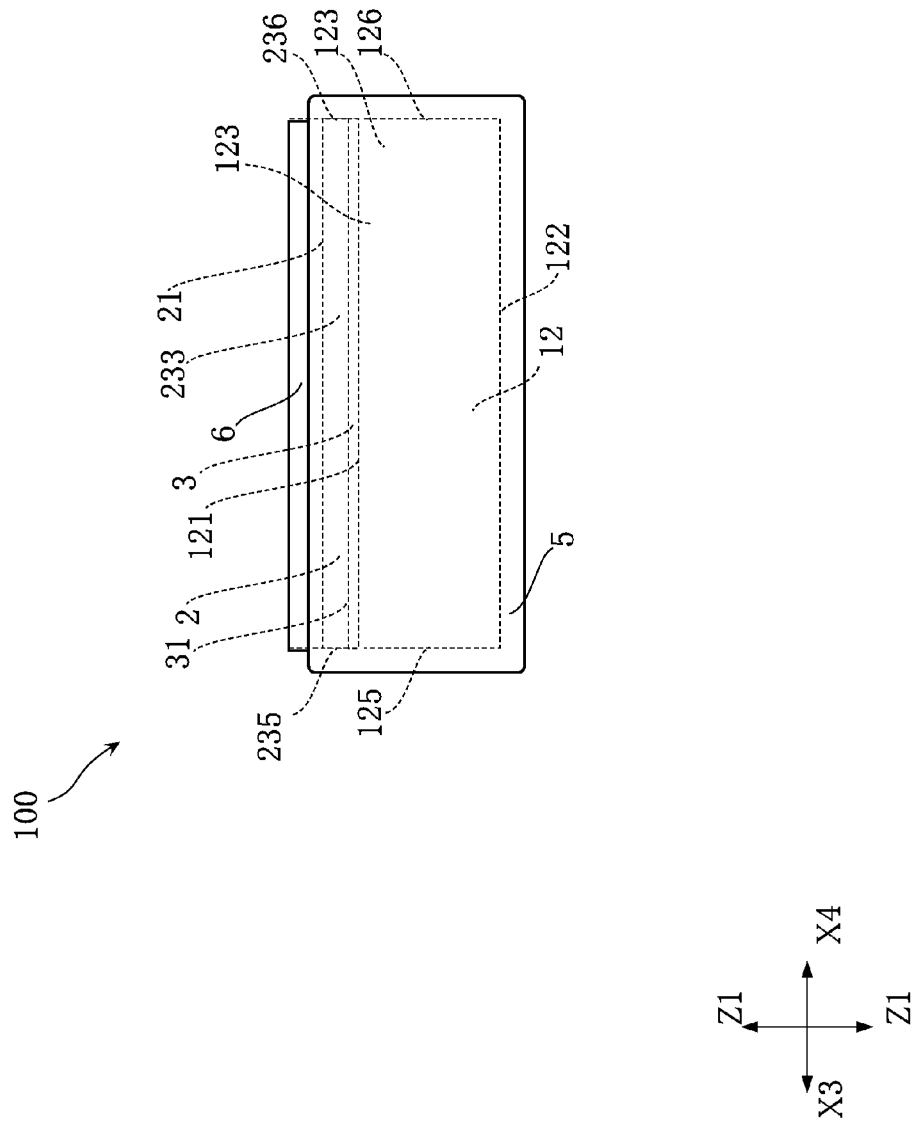
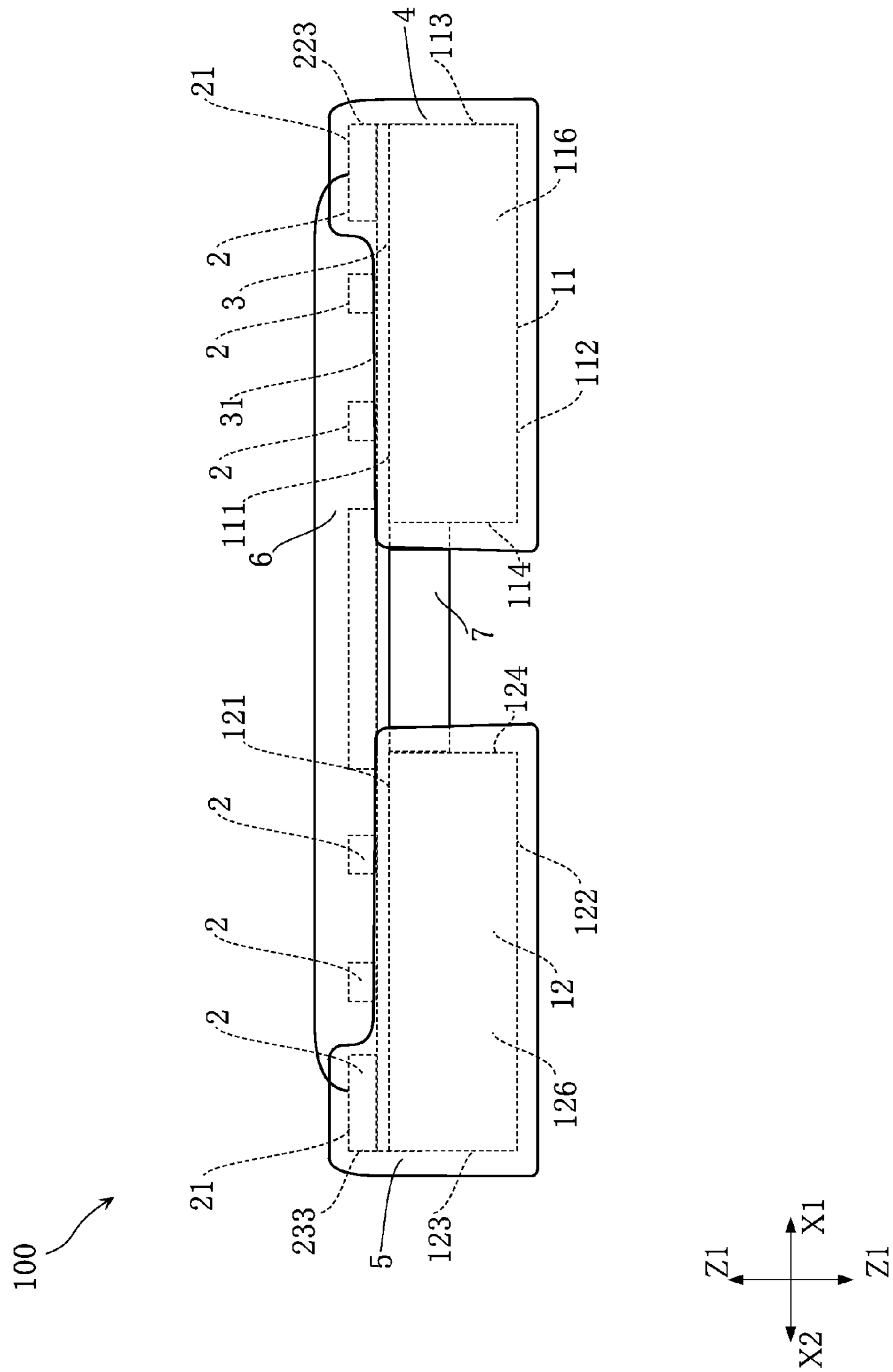


FIG.10



100
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223
4
113
116
2
3
2
31
11
112
2
111
6
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7
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121
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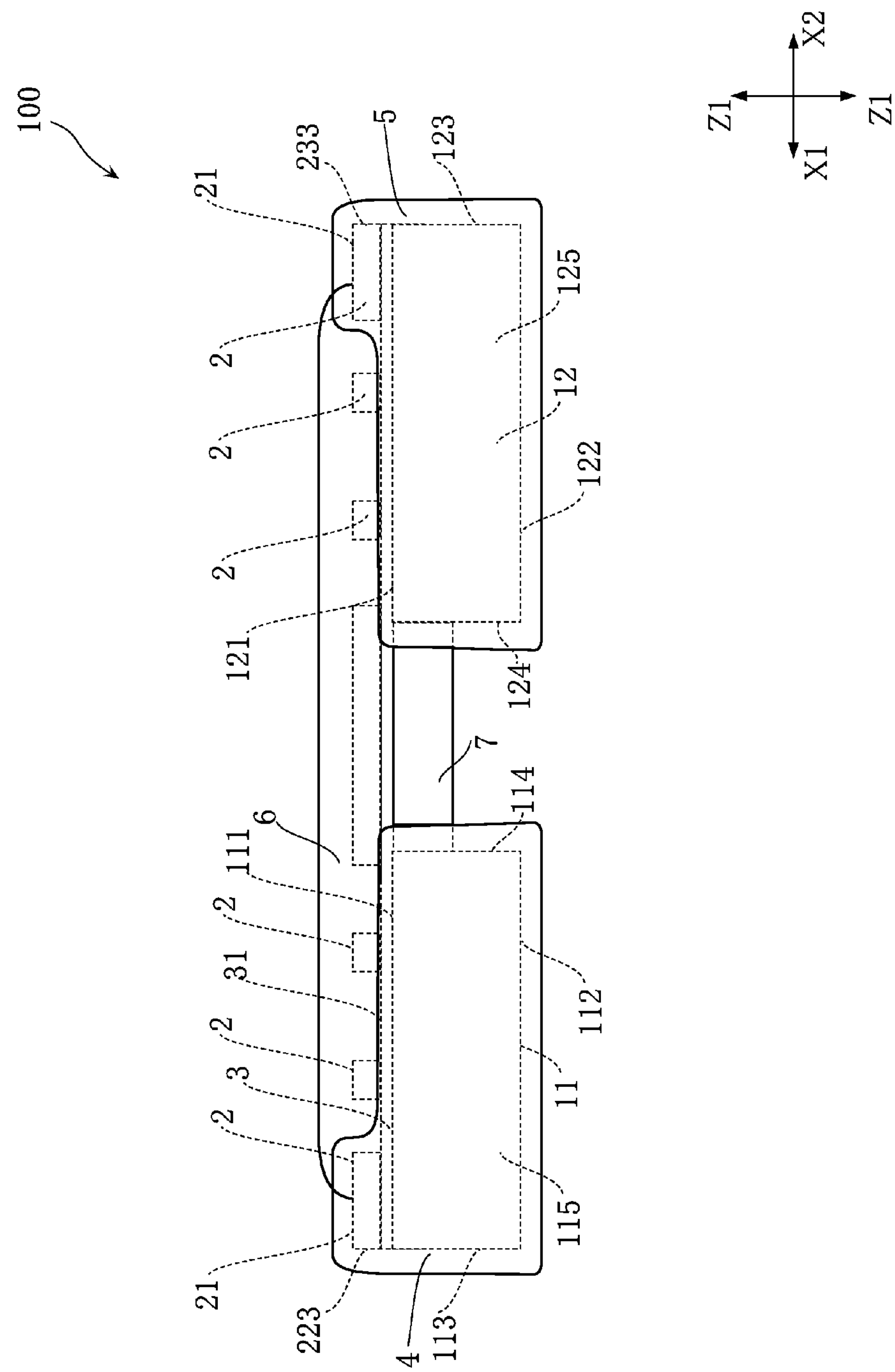
X1
Z1
Z1
X2


100
X2
X1
Z1
Z1
21
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5
123
125
2
2
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12
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121
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3
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112
11
115
21
223
4
113

FIG.11

FIG.12

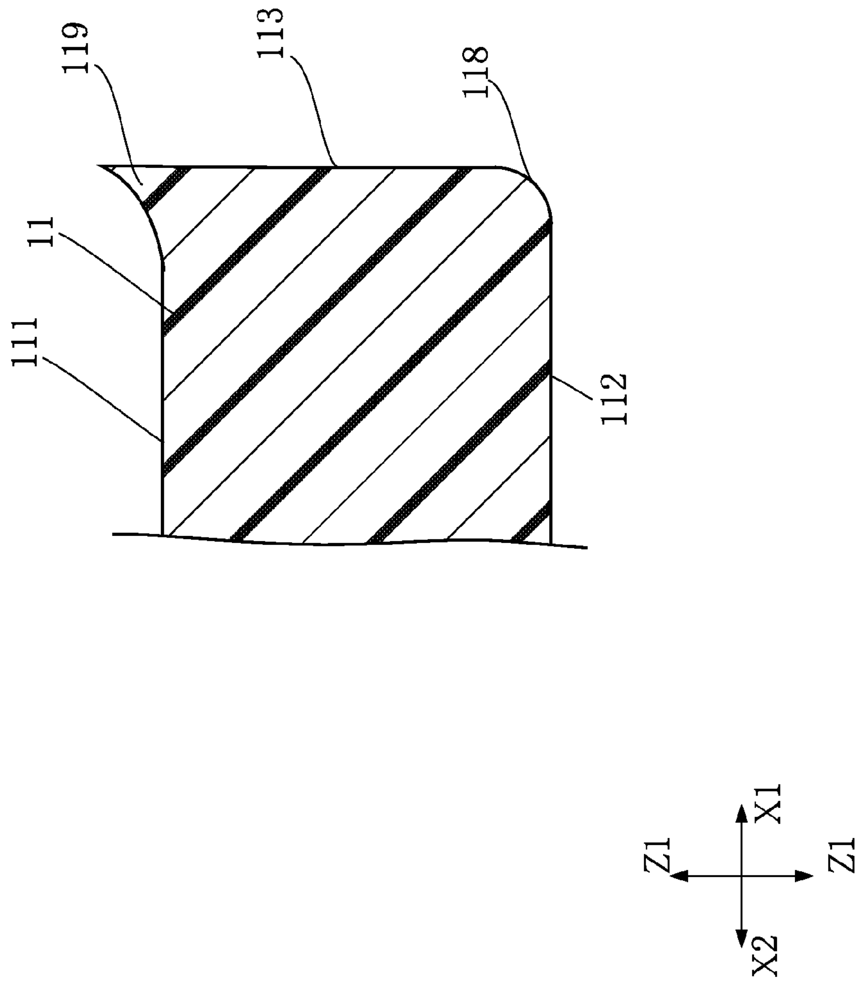
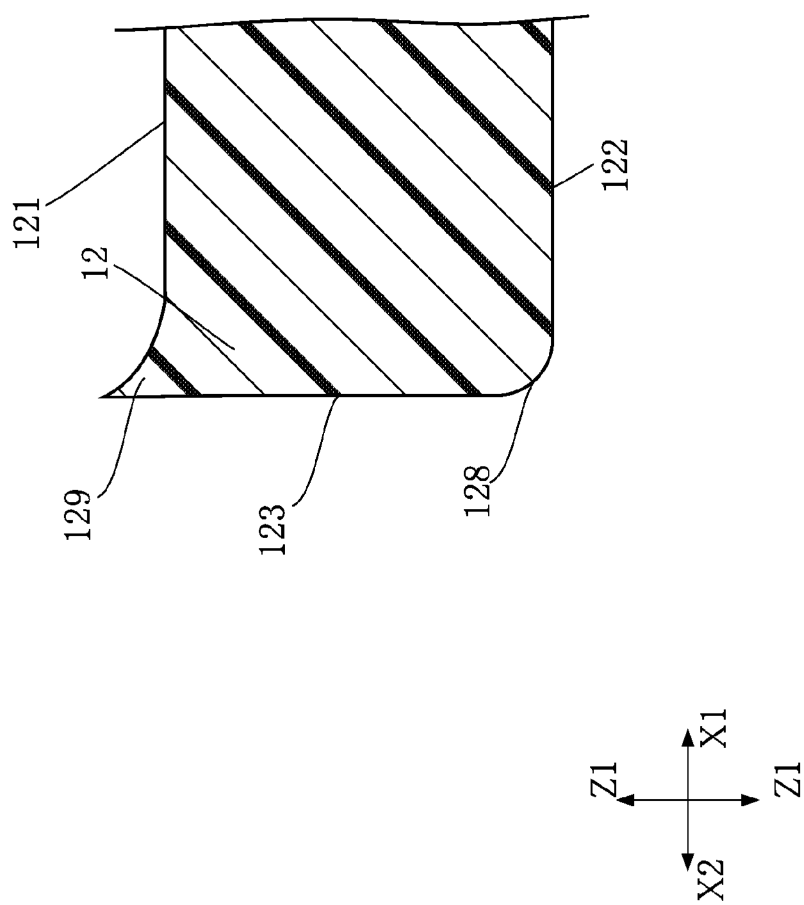


FIG.13



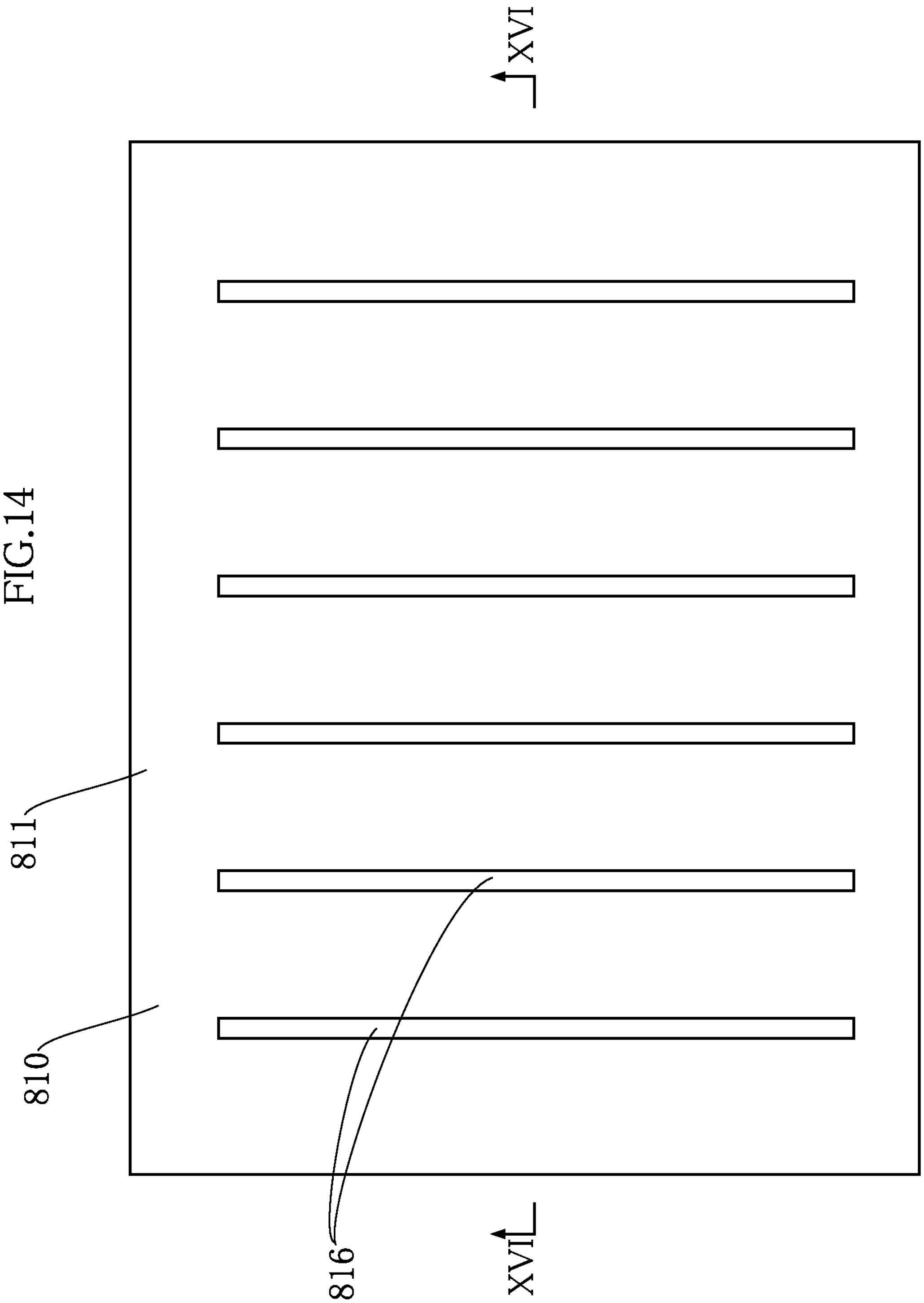


FIG.14

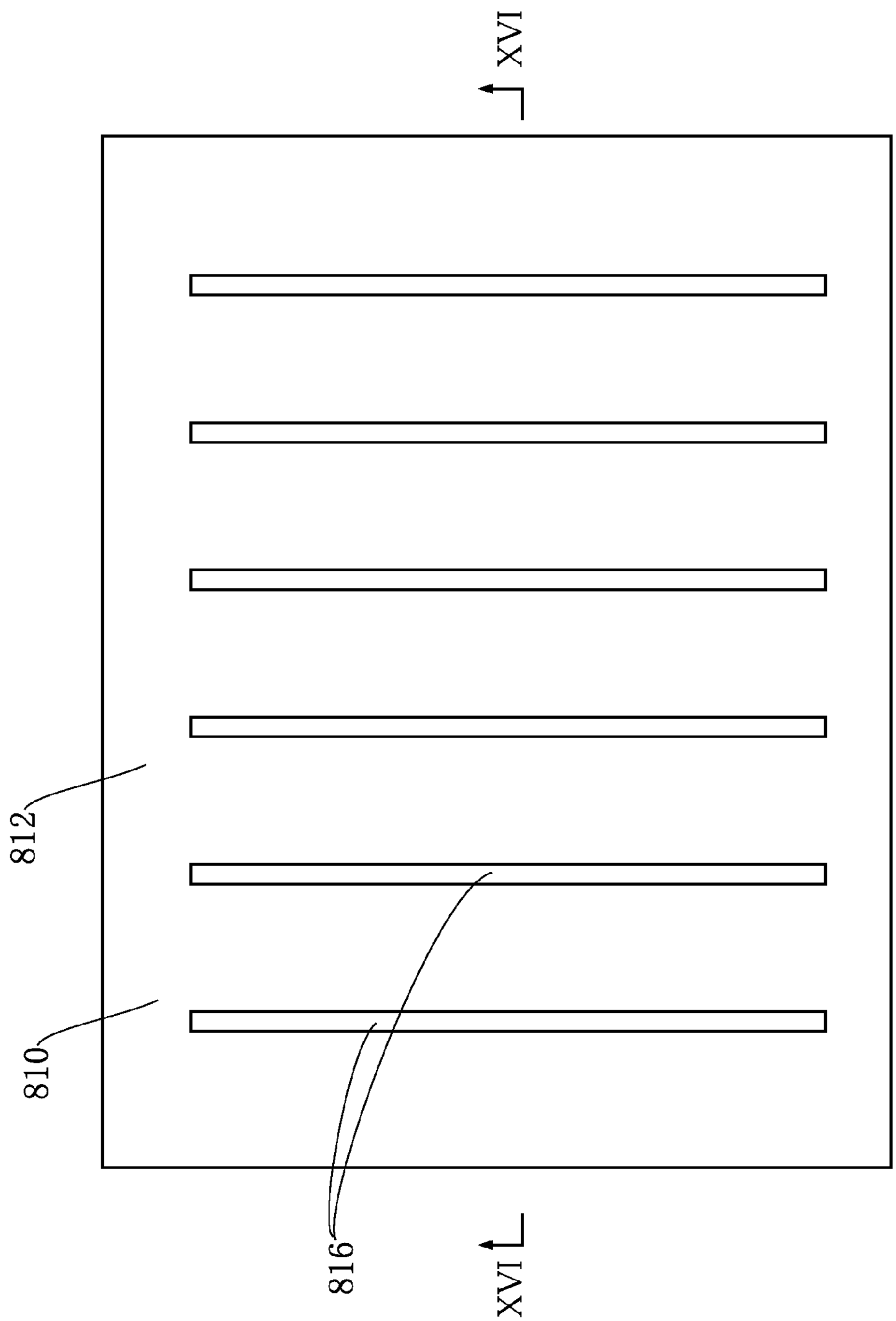
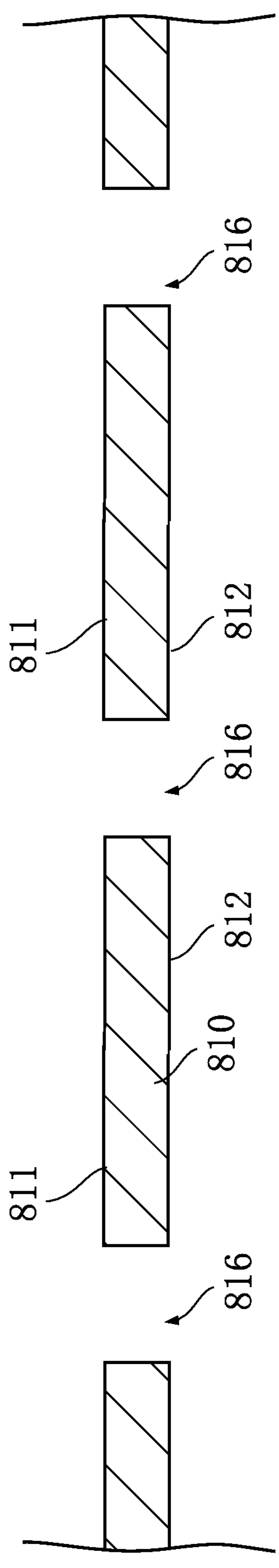


FIG.15

FIG.16



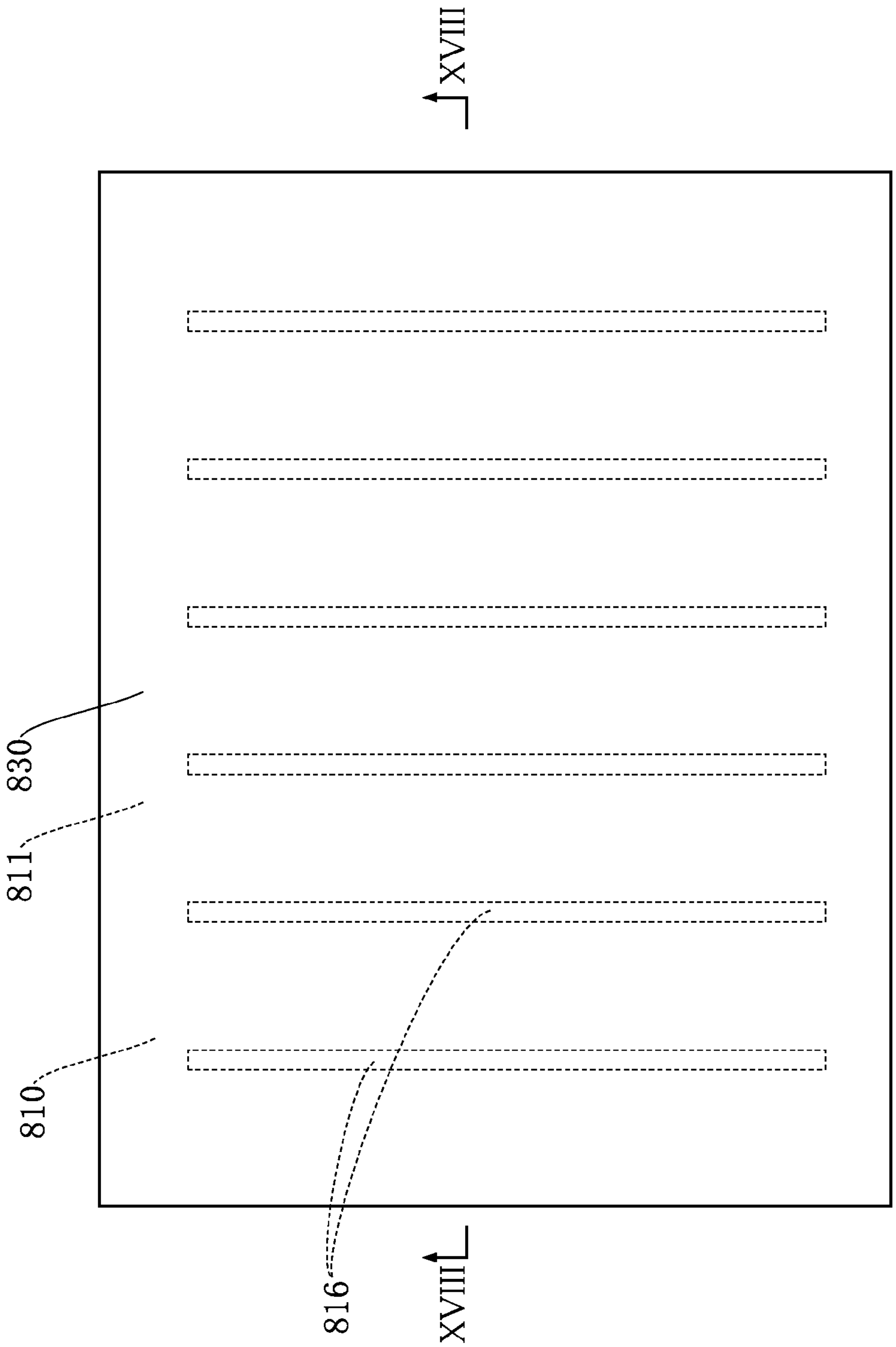


FIG.17

FIG.18

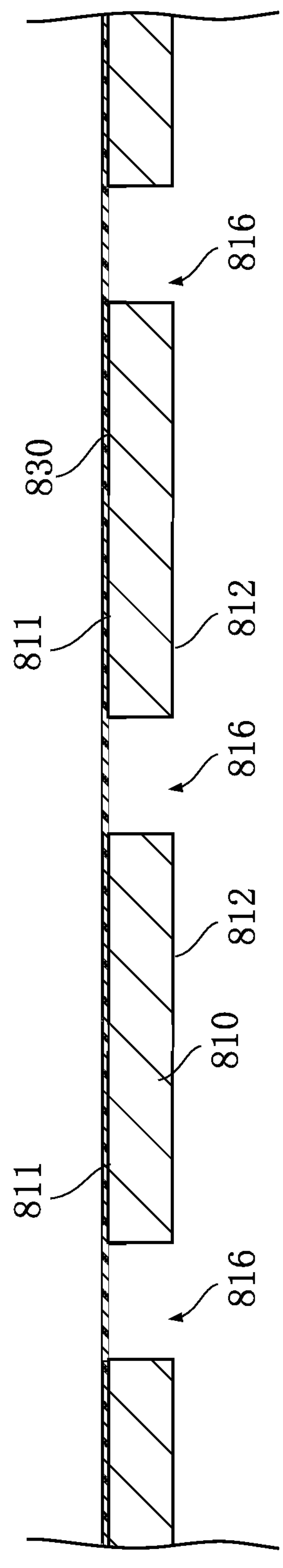


FIG.19

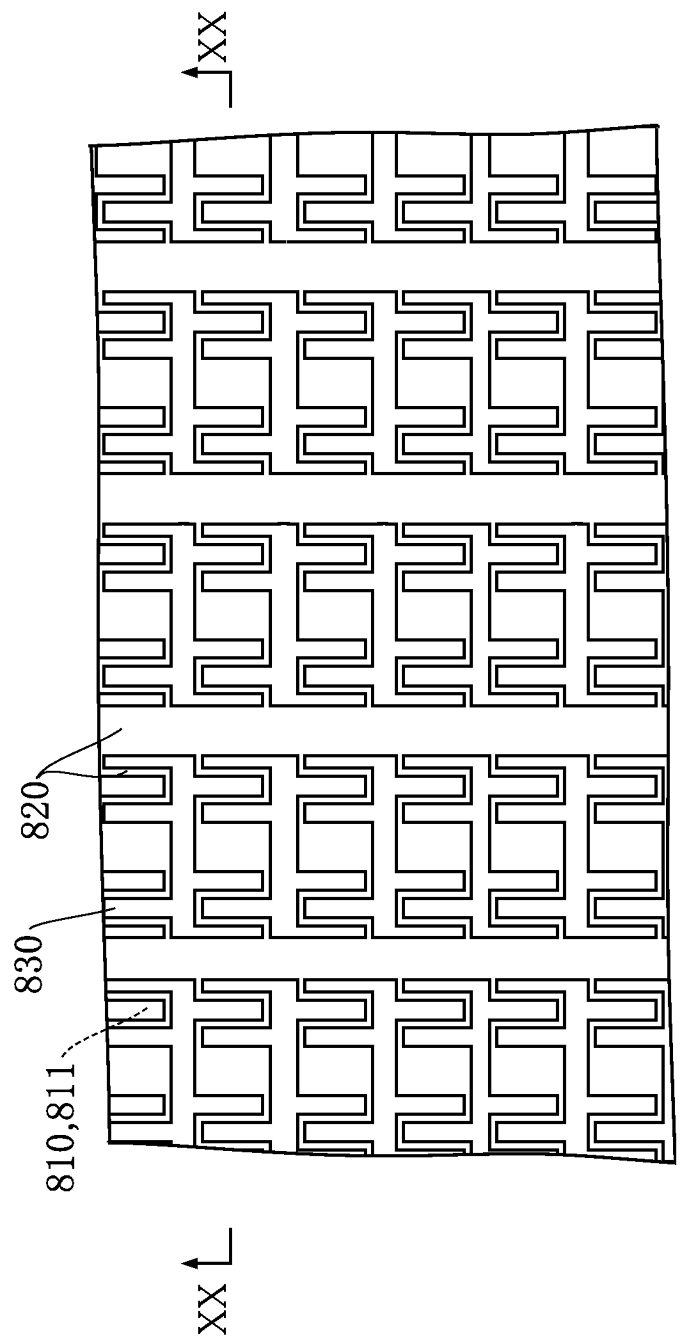


FIG.20

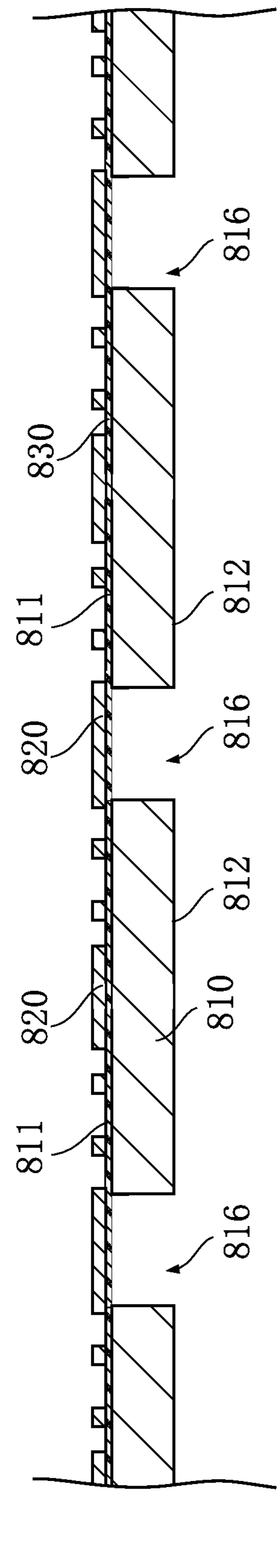


FIG.21

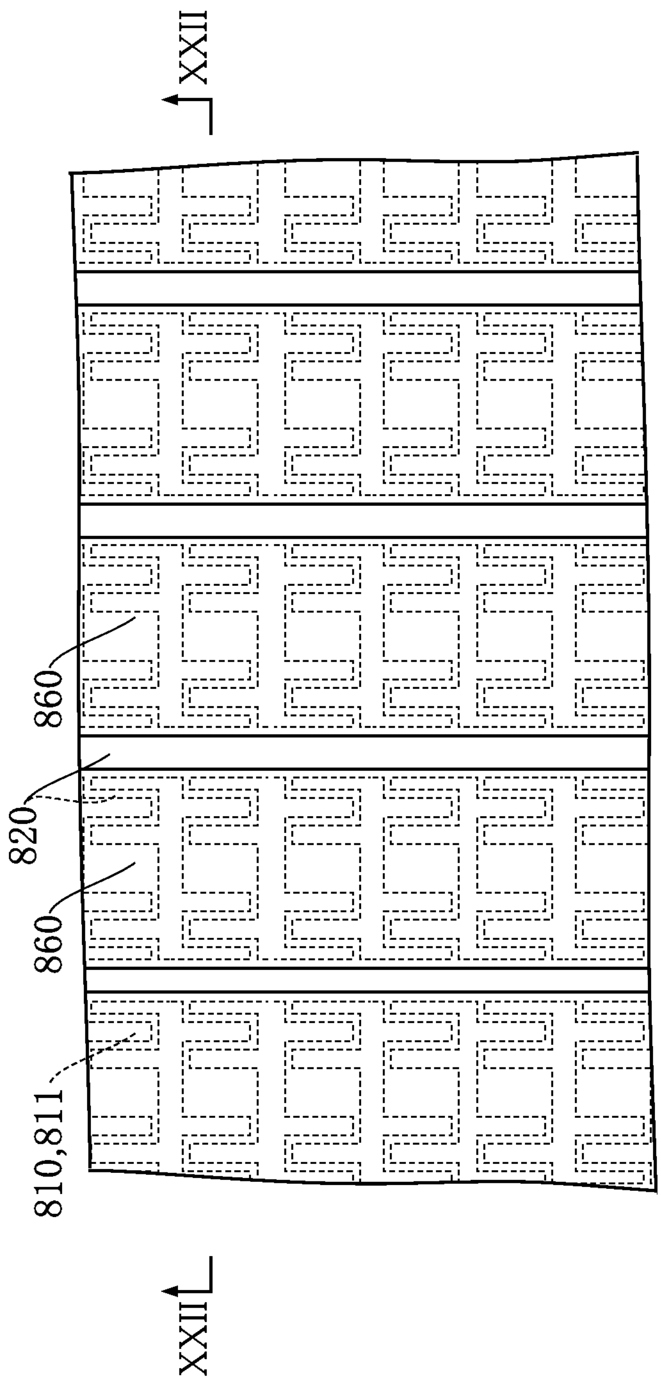


FIG.22

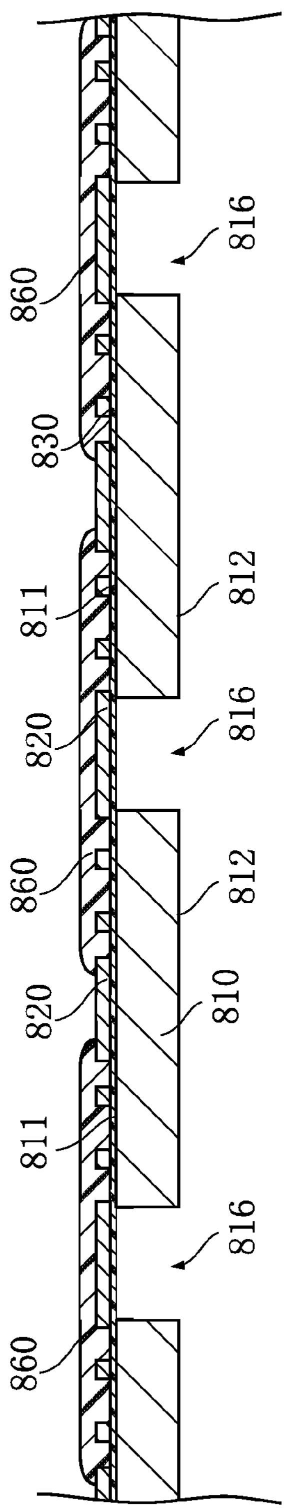


FIG.23

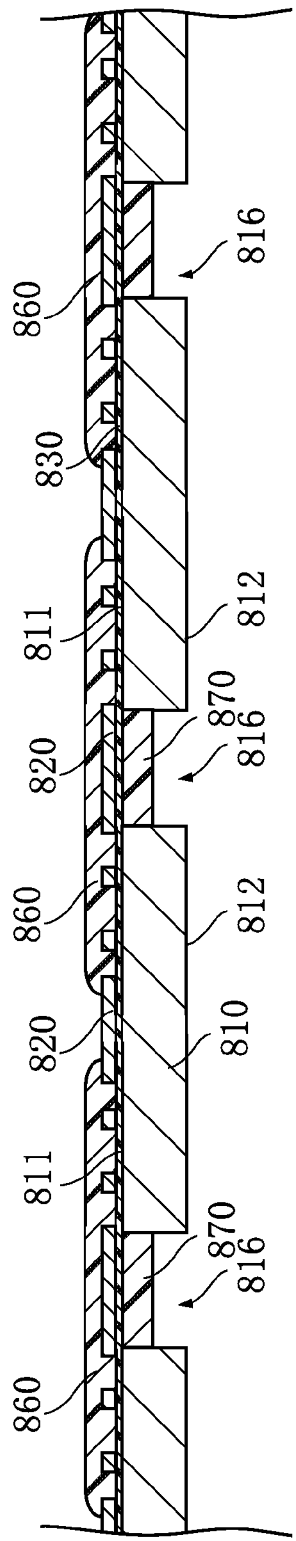
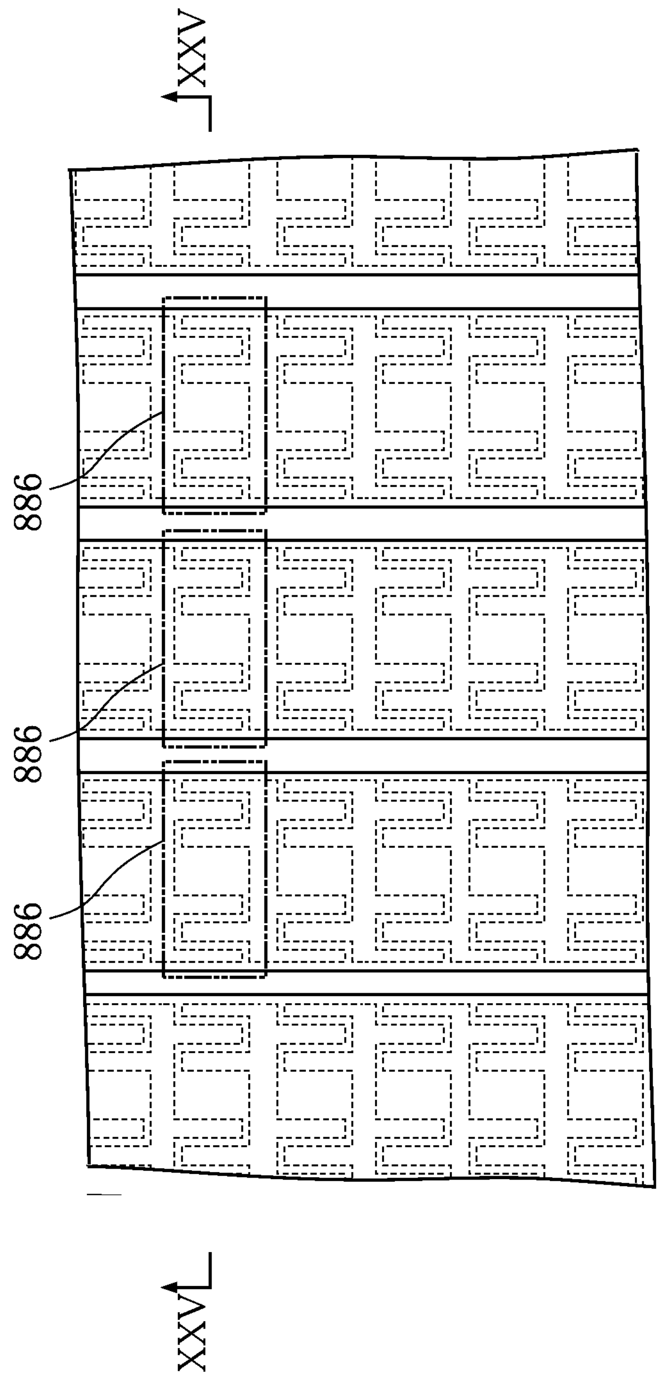


FIG.24



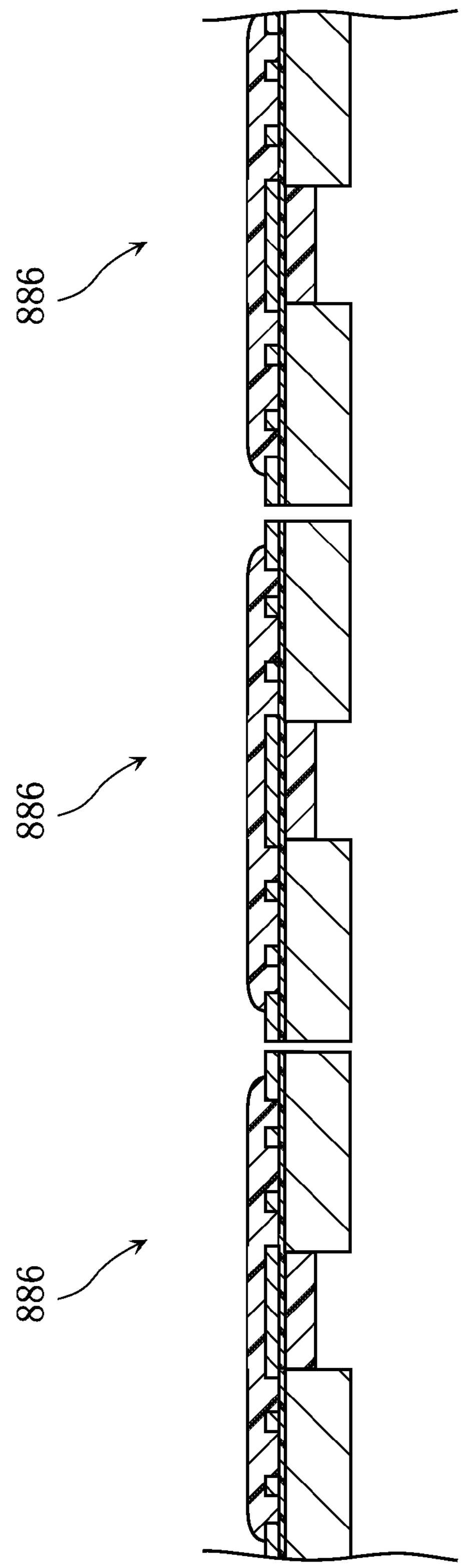


FIG.25

CHIP RESISTOR AND METHOD FOR MAKING THE SAME

BACKGROUND OF THE INVENTION

1. Field of the Invention

[0001] The present invention relates to a chip resistor and a method for making a chip resistor.

2. Description of the Related Art

[0002] Conventionally, chip resistors for use in electronic equipment are known. For instance, the chip resistor disclosed in JP-A-2009-218552 includes a resistor element made of metal and two electrodes. The two electrodes are provided on the resistor element as spaced apart from each other. To keep the strength of the chip resistor, the thickness of the resistor element as itself, which is made of metal, cannot be considerably reduced. Thus, in the conventional chip resistor, the resistance cannot be made sufficiently high.

SUMMARY OF THE INVENTION

[0003] The present invention has been conceived under the circumstances described above. It is therefore an object of the present invention to provide a chip resistor that can have increased resistance while keeping the strength.

[0004] According to a first aspect of the present invention, there is provided a chip resistor that includes: a first electrode and a second electrode spaced apart from each other, the first electrode being offset from the second electrode in a first direction, the second electrode being offset from the first electrode in a second direction opposite from a first direction; a resistor element arranged on the first electrode and the second electrode; a bonding layer provided between the first electrode and the resistor element and between the second electrode and the resistor element; and a first plating layer electrically connected to the resistor element. The first electrode includes a flat first-electrode outer side surface. The resistor element includes a first resistor-element side surface facing in the first direction. The first-electrode outer side surface is flush with the first resistor-element side surface. The first-electrode outer side surface includes two edges spaced apart from each other in a third direction perpendicular to both the first direction and a thickness direction of the first electrode. The first plating layer includes a portion directly covering at least a part of the first-electrode outer side surface, where the above-mentioned portion of the first plating layer extends continuously from one of the two edges to the other of the two edges.

[0005] Preferably, the first electrode includes a first-electrode obverse surface on which the resistor element is arranged and a first-electrode reverse surface facing away from the first-electrode obverse surface. The first plating layer directly covers the first-electrode reverse surface.

[0006] Preferably, the first electrode includes two first-electrode end surfaces facing away from each other, where one of the two first-electrode end surfaces faces in the third direction, and the first plating layer directly covers the two first-electrode end surfaces.

[0007] Preferably, the first electrode includes a first-electrode inner side surface facing toward the second electrode, and the first plating layer directly covers the first-electrode inner side surface.

[0008] Preferably, the first electrode includes an end that is disposed on a side of the first direction and formed with a sharp portion pointed in the first direction.

[0009] Preferably, the sharp portion of the first electrode is provided at the first-electrode obverse surface, and the first electrode includes a first curved surface connecting the first-electrode reverse surface and the first-electrode outer side surface to each other.

[0010] Preferably, the resistor element includes a serpentine portion.

[0011] Preferably, the bonding layer includes a bonding layer obverse surface held in direct contact with the resistor element.

[0012] Preferably, the first plating layer includes an inner plating film and an outer plating film, where the inner plating film directly covers the first electrode.

[0013] Preferably, the first plating layer includes an intermediate plating film disposed between the inner plating film and the outer plating film.

[0014] Preferably, the inner plating film is made of one of Cu, Ag and Au, the outer plating film is made of Sn, and the intermediate plating film is made of Ni.

[0015] Preferably, the chip resistor according to the first aspect of the present invention further includes a second plating layer electrically connected to the resistor element. The second electrode includes a flat second-electrode outer side surface, the resistor element includes a second resistor-element side surface facing in the second direction, and the second-electrode outer side surface is flush with the second resistor-element side surface. The second-electrode outer side surface includes two edges spaced apart from each other in the third direction. The second plating layer includes a portion directly covering at least a part of the second-electrode outer side surface, where the above-mentioned portion of the second plating layer extends continuously from one of the two edges of the second-electrode outer side surface to the other of the two edges of the second-electrode outer side surface.

[0016] Preferably, the second electrode includes a second-electrode obverse surface on which the resistor element is arranged and a second-electrode reverse surface facing away from the second-electrode obverse surface, where the second plating layer directly covers the second-electrode reverse surface.

[0017] Preferably, the second electrode includes two second-electrode end surfaces facing away from each other, where one of the two second-electrode end surfaces faces in the third direction, and the second plating layer directly covers the two second-electrode end surfaces.

[0018] Preferably, the second electrode includes a second-electrode inner side surface facing toward the first electrode, and the second plating layer directly covers the second-electrode inner side surface.

[0019] Preferably, the second electrode includes an end that is disposed on a side of the second direction and formed with a sharp portion pointed in the thickness direction.

[0020] Preferably, the sharp portion of the second electrode is provided at the second-electrode obverse surface, and the second electrode includes a second curved surface connecting the second-electrode reverse surface and the second-electrode outer side surface to each other.

[0021] Preferably, the chip resistor of the first aspect further includes an insulating protective film covering the resistor element, where the protective film is held in direct contact with the first plating layer.

[0022] Preferably, the chip resistor of the first aspect further includes an insulating heat conductive portion provided between the first electrode and the second electrode.

[0023] Preferably, the heat conductive portion is held in direct contact with the bonding layer.

[0024] Preferably, the first electrode and the second electrode are made of one of Cu, Ag, Au and Al.

[0025] Preferably, the bonding layer is made of an epoxy-based material.

[0026] Preferably, the resistor element is made of one of manganin, zeranin, Ni—Cr alloy, Cu—Ni alloy and Fe—Cr alloy.

[0027] According to a second aspect of the present invention, there is provided a method for making a chip resistor of the first aspect, where the method includes the steps of: preparing an electrically conductive base; and bonding a resistor element material to an obverse surface of the electrically conductive base by a bonding material.

[0028] Preferably, the base is formed with a plurality of grooves elongated in a direction.

[0029] Preferably, the bonding material is an adhesive sheet or a liquid adhesive.

[0030] Preferably, the method of the second aspect further includes the step of forming an insulating protective film covering the resistor element material.

[0031] Preferably, the method of the second aspect further includes the step of providing a heat conductive portion in each of the grooves after the step of bonding the resistor element material.

[0032] Preferably, the method of the second aspect further includes the step of obtaining a plurality of individual pieces by cutting the base.

[0033] Preferably, the step of obtaining a plurality of individual pieces includes cutting the base by punching or dicing.

[0034] Preferably, the method of the second aspect further includes the step of forming a plating layer on each of the individual pieces.

[0035] Other features and advantages of the present invention will become more apparent from detailed description given below with reference to the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0036] FIG. **1** is a plan view of a chip resistor according to an embodiment of the present invention;

[0037] FIG. **2** is a sectional view taken along lines II-II in FIG. **1**;

[0038] FIG. **3** is a sectional view taken along lines in FIG. **1**;

[0039] FIG. **4** is a sectional view taken along lines IV-IV in FIG. **1**;

[0040] FIG. **5** is a sectional view taken along lines V-V in FIG. **1**;

[0041] FIG. **6** is a sectional view taken along lines VI-VI in FIG. **1**;

[0042] FIG. **7** is a plan view obtained by omitting a first plating layer and a second plating layer from FIG. **1**;

[0043] FIG. **8** is a right side view of the chip resistor shown in FIG. **1**;

[0044] FIG. **9** is a left side view of the chip resistor shown in FIG. **1**;

[0045] FIG. **10** is a front view of the chip resistor shown in FIG. **1**;

[0046] FIG. **11** is a rear view of the chip resistor shown in FIG. **1**;

[0047] FIG. **12** is a sectional view showing the first electrode **11** of the embodiment of the present invention;

[0048] FIG. **13** is a sectional view showing the second electrode **11** of the embodiment of the present invention;

[0049] FIG. **14** is a plan view showing a step of a method for making the chip resistor shown in FIG. **1**;

[0050] FIG. **15** is a reverse side view showing a step of a method for making the chip resistor shown in FIG. **1**;

[0051] FIG. **16** is a sectional view taken along lines XVI-XVI in FIGS. **14** and **15**;

[0052] FIG. **17** is a plan view showing a step subsequent to FIGS. **14**-**16**;

[0053] FIG. **18** is a sectional view taken along lines XVIII-XVIII in FIG. **17**;

[0054] FIG. **19** is partially enlarged plan view showing a step subsequent to FIG. **17**;

[0055] FIG. **20** is a sectional view taken along lines XX-XX in FIG. **19**;

[0056] FIG. **21** is partially enlarged plan view showing a step subsequent to FIG. **19**;

[0057] FIG. **22** is a sectional view taken along lines XXII-XXII in FIG. **21**;

[0058] FIG. **23** is a sectional view showing a step subsequent to FIG. **22**;

[0059] FIG. **24** is partially enlarged plan view showing a step subsequent to FIG. **22**; and

[0060] FIG. **25** is a sectional view taken along lines XXV-XXV in FIG. **24**.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0061] Embodiments of the present invention are described below with reference to the accompanying drawings.

[0062] FIGS. **1**-**13** depict a chip resistor according to an embodiment of the present invention. The illustrated chip resistor **100** includes a first electrode **11**, a second electrode **12**, a resistor element **2**, a bonding layer **3**, a first plating layer **4**, a second plating layer **5** and a protective film **6**.

[0063] The first electrode **11** is in the form of a plate. The first electrode **11** is made of an electrically conductive material such as Cu, Ag, Au and Al. Heat generated at the resistor element **2** dissipates to the outside of the chip resistor **100** through the first electrode **11**. In FIG. **2**, the thickness direction of the first electrode **11** is indicated by arrows Z**1**. In FIG. **1**, the first direction (corresponding to the right direction in the figure) is indicated by an arrow X**1**, and the second direction (corresponding to the left direction in the figure) is indicated by an arrow X**2**. Further, the third direction (corresponding to the upward direction in the figure) is indicated by an arrow X**3**, and the fourth direction (corresponding to the downward direction in the figure) is indicated by an arrow X**4**.

[0064] In the illustrated embodiment, the thickness (the dimension measured in the thickness direction Z**1**) of the first electrode **11** may be 200-800 μm. The length (the dimension measured in the first direction X**1**) of the chip resistor **100** may be 3-10 mm, and the width (the dimension measured in the third direction X**3**) of the chip resistor **100** may be 1-10 mm.

[0065] The first electrode **11** includes an obverse surface **111** (called "first-electrode obverse surface **111**" below), a reverse surface **112** (called "first-electrode reverse surface **112**" below), an outer side surface **113** (called "first-electrode outer side surface **113**" below), an inner side surface **114** (called "first-electrode inner side surface **114**" below), an end surface **115** (called "first-electrode end surface **115**" below) **115** and an end surface **116** (called "first-electrode end surface **116**" below). In the illustrated example, at least the first-electrode obverse surface **111**, the first-electrode reverse surface **112**, the first-electrode outer side surface **113**, the first-electrode end surface **115** and the first-electrode end surface **116** are flat.

[0066] The first-electrode obverse surface **111** and the first-electrode reverse surface **112** face away from each other. The first-electrode obverse surface **111** faces to one side in the thickness direction Z**1** (or, faces in one sense of the thickness direction Z**1**), whereas the first-electrode reverse surface **11** faces to the other side in the thickness direction Z**1**. The first-electrode outer side surface **113** faces in the first direction X**1**. The first-electrode inner side surface **114** faces in the second direction X**2**. Thus, the first-electrode outer side surface **113** and the first-electrode inner side surface **114** face away from each other. The first-electrode inner side surface **114** faces toward the second electrode **12**. The first-electrode end surface **115** faces in the third direction X**3**. The first-electrode end surface **116** faces in the fourth direction X**4**. Thus, the first-electrode end surface **115** and the first-electrode end surface **116** face away from each other.

[0067] FIG. **12** is a sectional view showing the first electrode **11**. As shown, the first electrode **11** includes a sharp portion **119** pointed to one side in the thickness direction Z**1**. The sharp portion **119** is provided at an end of the first electrode **11** in the first direction X**1**. In the illustrated example, the sharp portion **119** is provided at the obverse surface **111**. In the illustrated example, the first electrode **11** further includes a first curved surface **118**. The first curved surface **118** connects the first-electrode reverse surface **112** and the first-electrode outer side surface **113** to each other. In the illustrated example, the first curved surface **118** also connects the first-electrode reverse surface **112** and the first-electrode end surface **115** to each other and the first-electrode reverse surface **112** and the first-electrode end surface **116** to each other.

[0068] The second electrode **12** is spaced apart from the first electrode **11**. Specifically, the second electrode **12** is spaced apart from the first electrode **11** in the second direction X**2**, opposite to the first direction X**1**. The second electrode **12** is in the form of a plate. The second electrode **12** is made of an electrically conductive material such as Cu, Ag, Au and Al. Heat generated at the resistor element **2** dissipates to the outside of the chip resistor **100** through the second electrode **12**.

[0069] In the illustrated embodiment, the thickness (the dimension measured in the thickness direction Z**1**) of the second electrode **12** may be 200-800 μm.

[0070] The second electrode **12** includes a second-electrode obverse surface **121**, a second-electrode reverse surface **122**, a second-electrode outer side surface **123**, a second-electrode inner side surface **124**, a second-electrode end surface **125** and a second-electrode end surface **126**. In the illustrated example, at least the second-electrode obverse surface **121**, the second-electrode reverse surface **122**, the second-electrode outer side surface **123**, the second-electrode end surface **125** and the second-electrode end surface **126** are flat.

[0071] The second-electrode obverse surface **121** and the second-electrode reverse surface **122** face away from each other. The second-electrode obverse surface **121** faces to one side in the thickness direction Z**1**, whereas the second-electrode reverse surface **122** faces to the other side in the thickness direction Z**1**. The second-electrode outer side surface **123** faces in the second direction X**2**. The second-electrode inner side surface **124** faces in the first direction X**1**. Thus, the second-electrode outer side surface **123** and the second-electrode inner side surface **124** face away from each other. The second-electrode inner side surface **124** faces toward the first electrode **11**. In the illustrated example, apart of the second-electrode inner side surface **124** faces a part of the first-electrode inner side surface **114**. The second-electrode end surface **125** faces in the third direction X**3**. The second-electrode end surface **126** faces in the fourth direction X**4**. Thus, the second-electrode end surface **125** and second-electrode end surface **126** face away from each other.

[0072] FIG. **13** is a sectional view showing the second electrode **12**. In the illustrated example, as shown in FIG. **13**, the second electrode **12** includes a sharp portion **129** pointed to one side in the thickness direction Z**1**. The sharp portion **129** is provided at an end of the second electrode **12** in the second direction X**2**. In the illustrated example, the sharp portion **129** is provided at the obverse surface **121**. In the illustrated example, the second electrode **12** further includes a second curved surface **128**. The second curved surface **128** connects the second-electrode reverse surface **112** and the second-electrode outer side surface **123** to each other. In the illustrated example, the second curved surface **128** also connects the second-electrode reverse surface **122** and the second-electrode end surface **125** to each other and the second-electrode reverse surface **122** and the second-electrode end surface **126** to each other.

[0073] As shown in FIG. **2**, the resistor element **2** is provided on both the first electrode **11** and the second electrode **12**. Specifically, the resistor element **2** is arranged on the first-electrode obverse surface **111** of the first electrode **11** and also the second-electrode obverse surface **121** of the second electrode **12**. For instance, the thickness (the dimension measured in the thickness direction Z**1**) of the resistor element **2** is 50-150 μm. In the illustrated example, the resistor element **2** includes a serpentine portion, as viewed in the thickness direction Z**1**. The serpentine shape of the resistor element **2** is advantageous in increasing the resistance of the resistor element **2**. Alternatively, unlike the illustrated example, the resistor element **2** may not be in the form of a serpentine but may be in the form of a strip elongated straight in the X**1**-X**2** direction. The resistor element **2** is made of a resistive metal material such as manganin, zeranin, Ni—Cr alloy, Cu—Ni alloy or Fe—Cr alloy.

[0074] As shown in FIGS. **1** and **2**, the resistor element **2** includes an obverse surface ("resistor element obverse surface") **21**, a first side surface ("first resistor-element side surface") **223**, a first end surface ("first resistor-element end surface") **225**, a first end surface ("first resistor-element end surface") **226**, a second side surface ("second resistor-element side surface") **233**, a second end surface ("second resistor-element end surface") **235** and a second end surface ("second resistor-element end surface") **236**. In the illustrated example, all of the resistor element obverse surface **21**, the first resistor-element side surface **223**, the first resistor-element end surface **225**, the first resistor-element end surface **226**, the second resistor-element side surface **233**, the second resistor-element end surface **235** and the second resistor-element end surface **236** are flat.

[0075] The resistor element obverse surface **21** faces to the upper side in FIG. **2**. The first resistor-element side surface **223** faces in the first direction X**1**. The first resistor-element side surface **223** is flush with the first-electrode outer side surface **113**. The first resistor-element end surface **225** faces in the third direction X**3**. The first resistor-element end surface **225** is flush with the first-electrode end surface **115**. The first resistor-element end surface **226** faces in the fourth direction X**4**. The first resistor-element end surface **226** is flush with the first-electrode end surface **116**. The second resistor-element side surface **233** faces in the second direction X**2**. The second resistor-element side surface **233** is flush with the second-electrode outer side surface **123**. The second resistor-element end surface **235** faces in the third direction X**3**. The second resistor-element end surface **235** is flush with the second-electrode end surface **125**. The second resistor-element end surface **236** faces in the fourth direction X**4**. The second resistor-element end surface **236** is flush with the second-electrode end surface **126**.

[0076] The bonding layer **3** is provided between the first electrode **11** and the resistor element **2** and also between the second electrode **12** and the resistor element **2**. Specifically, the bonding layer **3** is provided between the first-electrode obverse surface **111** of the first electrode **11** and the resistor element **2** and between the second-electrode obverse surface **121** of the second electrode **12** and the resistor element **2**. The bonding layer **3** bonds the resistor element **2** to the first-electrode obverse surface **111** and the second-electrode obverse surface **121**. Preferably, the bonding layer **3** is made of an insulating material. For instance, an epoxy-based material may be used as the insulating material. It is preferable that the material forming the bonding layer **3** has high thermal conductivity so that heat generated at the resistor element **2** easily dissipates to the outside of the chip resistor **100** through the bonding layer **3**. For instance, the thermal conductivity of the material forming the bonding layer **3** is 0.5-3.0 W/(m·K). For instance, the thickness (the dimension measured in the thickness direction Z1) of the bonding layer **3** is 30-100 μm. As shown in FIGS. **2-6**, in the illustrated example, the bonding layer **3** covers the entirety of the first-electrode obverse surface **111** and the entirety of the second-electrode obverse surface **121**.

[0077] Alternatively, unlike the illustrated example, the bonding layer **3** may be formed only at a part of the first-electrode obverse surface **111**. For instance, the bonding layer **3** may be formed only at a region of the first-electrode obverse surface **111** which overlaps the resistor element **2**. Similarly, the bonding layer **3** may be formed only at a part of the second-electrode obverse surface **121**. For instance, the bonding layer **3** may be formed only at a region of the second-electrode obverse surface **121** which overlaps the resistor element **2**.

[0078] As shown in FIGS. **2-6**, the bonding layer **3** has a bonding layer obverse surface **31**. The bonding layer obverse surface **31** faces in the same direction as the first-electrode obverse surface **111** (i.e., upward in FIG. **2**). The bonding layer obverse surface **31** is held in direct contact with the resistor element **2**.

[0079] As shown in FIG. **2**, the first plating layer **4** is electrically connected to the resistor element **2**. According to the present invention, the first plating layer **4** directly covers at least a part of the first-electrode outer side surface **113** in a manner such that the covering portion of the plating layer **4** extends continuously in the third direction X**3**, from one edge of the side surface **113** to the other edge of the same. In the illustrated example, the first plating layer **4** directly covers the entirety of the first-electrode outer side surface **113**. Also, in the illustrated example, the first plating layer **4** directly covers the first-electrode reverse surface **112**, the first-electrode inner side surface **114**, the first-electrode end surface **115** and the first-electrode end surface **116**. Unlike the illustrated example, the first plating layer **4** may not directly cover all of the first-electrode reverse surface **112**, the first-electrode inner side surface **114**, the first-electrode end surface **115** and the first-electrode end surface **116**. For instance, one or more of these surfaces may be exposed, partially or entirely, from the first plating layer **4**.

[0080] The first plating layer **4** includes a first inner plating film **41** and a first outer plating film **43**. For instance, the first inner plating film **41** is made of Cu, Ag or Au. The first inner plating film **41** directly covers the first-electrode outer side surface **113**. In the illustrated example, the first inner plating film **41** directly covers the entirety of the first-electrode outer side surface **113**. Also, in the illustrated example, the first inner plating film **41** directly covers the first-electrode reverse surface **112**, the first-electrode inner side surface **114**, the first-electrode end surface **115** and the first-electrode end surface **116**. The first outer plating film **43** is provided on the first inner plating film **41**. In mounting the chip resistor **100** to e.g., a printed circuit board, solder adheres to the first outer plating film **43**. The first outer plating film **43** is made of Sn, for example.

[0081] In the illustrated example, the first plating layer **4** includes a first intermediate plating film **42**. The first intermediate plating film **42** is provided between the first inner plating film **41** and the first outer plating film **43**. The first intermediate plating film **42** is made of Ni, for example. Unlike the illustrated example, the first plating layer **4** may not include the first intermediate plating film **42**, and the first inner plating film **41** and the first outer plating film **43** may be held in direct contact with each other.

[0082] The first inner plating film **41** maybe 10-50 μm in thickness, the first intermediate plating film **42** may be 1-10 μm in thickness and the first outer plating film **43** may be 1-10 μm in thickness.

[0083] As shown in FIG. **2**, the second plating layer **5** is electrically connected to the resistor element **2**. According to the present invention, the second plating layer **5** directly covers at least a part of the second-electrode outer side surface **123** in a manner such that the covering portion of the plating layer **5** extends continuously in the third direction X**3**, from one edge of the side surface **123** to the other edge of the same. In the illustrated example, the second plating layer **5** directly covers the entirety of the second-electrode outer side surface **123**. Also, in the illustrated example, the second plating layer **5** directly covers the second-electrode reverse surface **122**, the second-electrode inner side surface **124**, the second-electrode end surface **125** and the second-electrode end surface **126**. Unlike the illustrated example, the second plating layer **5** may not directly cover all of the second-electrode reverse surface **122**, the second-electrode inner side surface **124**, the second-electrode end surface **125**

and the second-electrode end surface **126**. For instance, one or more of these surfaces may be exposed, partially or entirely, from the second plating layer **5**.

[0084] The second plating layer **5** includes a second inner plating film **51** and a second outer plating film **53**. For instance, the second inner plating film **51** is made of Cu, Ag or Au. The second inner plating film **51** directly covers the second-electrode outer side surface **123**. In the illustrated example, the second inner plating film **51** directly covers the entirety of the second-electrode outer side surface **123**. Also, the second inner plating film **51** directly covers the second-electrode reverse surface **122**, the second-electrode inner side surface **124**, the second-electrode end surface **125** and the second-electrode end surface **126**. The second outer plating film **53** is provided on the second inner plating film **51**. In mounting the chip resistor **100** to e.g., a printed circuit board, solder adheres to the second outer plating film **53**. The second outer plating film **53** is made of Sn, for example.

[0085] In the illustrated example, the second plating layer **5** includes a second intermediate plating film **52**. The second intermediate plating film **52** is provided between the second inner plating film **51** and the second outer plating film **53**. For instance, the second intermediate plating film **52** is made of Ni. Unlike the illustrated example, the second plating layer **5** may not include the second intermediate plating film **52**, and the second inner plating film **51** and the second outer plating film **53** may be held in direct contact with each other.

[0086] The second inner plating film **51** may be 10-50 μm in thickness, the second intermediate plating film **52** may be 1-10 μm in thickness and the second outer plating film **53** may be 1-10 μm in thickness.

[0087] The protective film **6** has insulating properties and covers the resistor element **2**. The protective film **6** is made of an epoxy-based material. In the illustrated example, the protective film **6** directly covers the bonding layer **3** (specifically, the bonding layer obverse surface **31** of the bonding layer **3**). The protective film **6** is held in contact with the first plating layer **4** and the second plating layer **5**. The protective film **6** may be made of a thermosetting material. The maximum thickness of the protective film **6** (the maximum dimension measured in the thickness direction Z1) may be 100-250 μm.

[0088] The heat conductive portion **7** has insulating properties and is provided between the first electrode **11** and the second electrode **12**. The heat conductive portion **7** is made of an epoxy-based material. In the illustrated example, the heat conductive portion **7** directly covers the bonding layer **3** (specifically, the reverse surface of the bonding layer **3**). The heat conductive portion **7** is held in direct contact with the first-electrode inner side surface **114** of the first electrode **11** and the second-electrode inner side surface **124** of the second electrode **12**. For instance, the heat conductive portion **7** is made of a thermosetting material. In the illustrated example, the heat conductive portion **7** is held in direct contact with the first plating layer **4** and the second plating layer **5**. In order that heat generated at the resistor element **2** can easily dissipate to the outside of the chip resistor **100** through the heat conductive portion **7**, it is preferable that the thermal conductivity of the material forming the heat conductive portion **7** is higher than that of the material forming the protective film **6**. For instance, the thermal conductivity of the material forming the heat conductive portion **7** is 0.5-3.0 W/(m·K).

[0089] A method for making the chip resistor **100** is described below.

[0090] First, as shown in FIGS. **14-16**, abase **810** is prepared. FIG. **14** shows the base obverse surface **811** of the base **810**. FIG. **15** shows the base reverse surface **812** of the base **810**. The base **810** is to become the above-described first electrode **11** and second electrode **12**. The base **810** is made of an electrically conductive material such as Cu, Ag, Au and Al. The base **810** is formed with a plurality of grooves **816**. Each groove **816** is elongated in one direction. The groove **816** penetrates the base **810** from the base obverse surface **811** to the base reverse surface **812**. The inner surfaces of the groove **816** are to become the above-described first-electrode inner side surface **114** and the second-electrode inner side surface **124**. The grooves **816** are formed by etching or punching, for example.

[0091] Then, as shown in FIGS. **17** and **18**, a bonding material **830** is attached to the base obverse surface **811** of the base **810**. The bonding material **830** is to become the above-described bonding layer **3**. In the illustrated example, the bonding material **830** is a heat conductive adhesive sheet. In the state shown in FIGS. **17** and **18**, the bonding material **830** is temporarily bonded to the base obverse surface **811** of the base **810** by thermocompression bonding. Part of the bonding material **830** may be provided in the grooves **816**.

[0092] Then, as shown in FIGS. **19** and **20**, the resistor element material **820** is bonded to the base obverse surface **811** by the bonding material **830**. In the illustrated example, in the state shown in FIGS. **19** and **20**, the resistor element material **820** is temporarily pressure-bonded to the bonding material **830**. The resistor element material **820** has a plurality of portions which are to become the above-described resistor elements **2**. In the illustrated example, to make the resistor element **2** in the form of a serpentine, a plurality of serpentine portions are formed in the resistor element material **820** by etching or with a punching die before the resistor element material **820** is bonded to the base obverse surface **811**.

[0093] Unlike the illustrated example, the resistor element material **820** may be bonded to the base obverse surface **811** of the base **810** by using a liquid adhesive as the bonding material **830**, instead of a sheet member.

[0094] Then, the resistor element material **820** is subjected to trimming (not shown) for adjusting the resistance of the resistor element **2**. For instance, the trimming is performed by using laser, a sandblast, a dicer or a grinder.

[0095] Then, as shown in FIGS. **21** and **22**, an insulating protective film **860** is formed. The protective film **860** is to become the above-described protective film **6**. The protective film **860** is formed as a plurality of strips elongated in one direction. For instance, the protective film **860** is formed by printing or other application methods.

[0096] Then, as shown in FIG. **23**, heat conductive portions **870** are formed. The heat conductive portions **870** are to become the above-described heat conductive portions **7**. The heat conductive portions **870** are formed in the grooves **816**, respectively, each of which is in the form of a strip elongated in one direction. For instance, the heat conductive portions **870** are formed by printing or other application methods.

[0097] Then, though not illustrated, the intermediate product shown in FIG. **23** is hardened at e.g. 150-200° C.

[0098] Then, as shown in FIGS. **24** and **25**, a plurality of individual pieces **886** are obtained from the intermediate product shown in FIG. **23**. Specifically, the individual pieces **886** are obtained by cutting the base **810**. In FIG. **24**, the portions to become the individual pieces **886** are indicated by double-dashed lines. In the step to obtain the individual pieces **886**, the base **810** is cut by punching or dicing. By cutting the base **810**, the first-electrode outer side surface **113**, first-electrode end surface **115** and first-electrode end surface **116** of the first electrode **11**, the second-electrode outer side surface **123**, second-electrode end surface **125** and second-electrode end surface **126** of the second electrode **12**, and the first resistor-element side surface **223**, first resistor-element end surface **225**, first resistor-element end surface **226**, second resistor-element side surface **233**, second resistor-element end surface **235** and second resistor-element end surface **236** of the resistor element **2** are formed.

[0099] When punching is used to produce the individual pieces **886**, force is applied to the base **810** and the resistor element material **820** by the punching die (not shown). Thus, the shape of the first electrode **11** or the second electrode **12** may not become a complete rectangular parallelepiped. For instance, the sharp portion **119** and the first curved surface **118** maybe formed at the first electrode **11** as shown in FIG. **12** or the sharp portions **129** and the second curved surface **128** may be formed at the second electrode **12** as shown in FIG. **13**.

[0100] Since the base **810** and the resistor element material **820** are cut at the same time, the first-electrode outer side surface **113** and the first resistor-element side surface **223** become flush with each other, as noted above. Since the base **810** and the resistor element material **820** are cut at the same time, the second-electrode outer side surface **123** and the second resistor-element side surface **233** become flush with each other, as noted above. Since the base **810** and the resistor element material **820** are cut at the same time, the first-electrode end surface **115**, the first resistor-element end surface **225**, the second-electrode end surface **125**, the second resistor-element end surface **235** become flush with each other, as noted above. Since the base **810** and the resistor element material **820** are cut at the same time, the first-electrode end surface **116**, the first resistor-element end surface **226**, the second-electrode end surface **126** and the second resistor-element end surface **236** become flush with each other, as noted above.

[0101] Then, the first plating layer **4** (first inner plating film **41**, first intermediate plating film **42** and first outer plating film **43**) and the second plating layer **5** (second inner plating film **51**, second intermediate plating film **52** and second outer plating film **53**) shown in e.g. FIG. **2** are formed on each individual piece **886**. For instance, the first plating layer **4** and the second plating layer **5** may be formed by electroplating. For instance, the first plating layer **4** and the second plating layer **5** may be formed by barrel plating. By performing the above-described steps, the chip resistor **100** is completed.

[0102] The advantages of the above-noted arrangements are described below.

[0103] As noted above, the chip resistor **100** includes the first electrode **11**, the second electrode **12**, the resistor element **2** and the bonding layer **3**. The resistor element **2** is arranged on the first electrode **11** and the second electrode **12**. The bonding layer **3** is provided between the first electrode **11** and the resistor element **2** and between the second electrode **12** and the resistor element **2**. According to this arrangement, the strength of the chip resistor **100** as a whole is maintained appropriately by the first electrode **11** and the second electrode **12** even when the thickness of the resistor element **2** is reduced. Thus, it is possible to increase the resistance of the resistor element **2** (resistance of the chip resistor **100**) while keeping the strength of the chip resistor **100**. That is, the chip resistor **100** can be structured as a high power resistor. The resistance of the chip resistor **100** is not lower than 10 mΩ.

[0104] According to the illustrated embodiment, the first-electrode outer side surface **113** is flush with the first resistor-element side surface **223**. Thus, unlike the arrangement in which the first resistor-element side surface **223** is offset from the first-electrode outer side surface **113** in the second direction X2, the first electrode **11** can be provided without the need for forming an electrode to connect the first electrode **11** and the resistor element **2** to each other in addition to the plating layer **4**. This enhances the manufacturing efficiency of the chip resistor **100**.

[0105] Likewise, the second-electrode outer side surface **123** is flush with the second resistor-element side surface **233**. Thus, unlike the arrangement in which the second resistor-element side surface **233** is offset from the second-electrode outer side surface **123** in the first direction X1, the second electrode **12** can be provided without the need for forming an electrode to electrically connect the second electrode **12** and the resistor element **2** to each other in addition to the plating layer **4**. This enhances the manufacturing efficiency of the chip resistor **100**.

[0106] The present invention is not limited to the foregoing embodiment. The specific structure of each part of the present invention may be varied in many ways.

[0107] In the method described above, the grooves **816** are formed in the base **810** before the resistor element material **820** is bonded to the base **810**. However, the method for making the chip resistor **100** is not limited to this. For instance, the grooves **816** may be formed in the base **810** after the protective film **860** is formed.

1-31. (canceled)

32. A resistor comprising:

a first electrode including an obverse surface and a reverse surface that face opposite sides to each other;

a second electrode spaced apart from the first electrode, the second electrode including an obverse surface and a reverse surface that face opposite sides to each other, the first electrode being offset from the second electrode in a first direction, and the second electrode being offset from the first electrode in a second direction opposite to the first direction;

a first electrical insulator located between the first electrode and the second electrode, the first electrical insulator including an obverse surface and a reverse surface that face opposite sides to each other;

a second electrical insulator including an obverse surface and a reverse surface that face opposite sides to each other, the reverse surface of the second electrical insulator facing each of the obverse surfaces of the first electrode, the second electrode, and the first electrical insulator, the second electrical insulator having heat conductivity, the second electrical insulator including a first side surface facing in the first direction side, and a second side surface facing in the second direction side;

a resistor element located on the obverse surface of the second electrical insulator;

a first electrical conductor electrically connected, at the obverse surface side of the second electrical insulator, to the resistor element; and

a second electrical conductor electrically connected, at the obverse surface side of the second electrical insulator, to the resistor element,

wherein a distance between the reverse surface of the second electrical insulator and the reverse surface of the first electrode is larger than a distance between the reverse surface of the second electrical insulator and the reverse surface of the first electrical insulator,

a distance between the reverse surface of the second electrical insulator and the reverse surface of the second electrode is larger than the distance between the reverse surface of the second electrical insulator and the reverse surface of the first electrical insulator,

the first electrode includes a first exposed surface that is exposed from the first electrical insulator and that is located at the reverse surface side of the second electrical insulator,

the second electrode includes a second exposed surface that is exposed from the first electrical insulator and that is located at the reverse surface side of the second electrical insulator, the second exposed surface of the second electrode facing the first exposed surface of the first electrode,

the first electrical conductor is located on the obverse surface of the second electrical insulator, the first side surface of the second electrical insulator, the reverse surface of the first electrode, and the first exposed surface of the first electrode, and

the second electrical conductor is located on the obverse surface of the second electrical insulator, the second side surface of the second electrical insulator, the reverse surface of the second electrode, and the second exposed surface of the second electrode.

33. The resistor of claim **32**, wherein each of the first electrical conductor and the second electrical conductor is held in contact with the first electrical insulator.

34. The resistor of claim **32**, wherein each of the first electrical conductor and the second electrical conductor includes a portion located between the first exposed surface and the second exposed surface.

35. The resistor of claim **32**, wherein the resistor element is held in contact with the obverse surface of the second electrical insulator.

36. The resistor of claim **32**, wherein the first electrical conductor is held in contact with the reverse surface of the first electrode.

37. The resistor of claim **32**, wherein the first electrode includes two first-electrode end surfaces facing opposite sides to each other,

one of the two first-electrode end surfaces facing in a third direction, the third direction being perpendicular to the first direction and the second direction, and

the first electrical conductor is located on the two first-electrode end surfaces.

38. The resistor of claim **32**, wherein the first electrical conductor is held in contact with the first exposed surface.

39. The resistor of claim **32**, wherein the resistor element comprises a serpentine portion.

40. The resistor of claim **32**, wherein the first electrical conductor includes an inner plating film and an outer plating film, and the inner plating film is held in contact with the first electrode.

41. The resistor of claim **40**, wherein the first electrical conductor includes an intermediate plating film located between the inner plating film and the outer plating film.

42. The resistor of claim **41**, wherein the inner plating film is made of one of Cu, Ag and Au, the outer plating film is made of Sn, and the intermediate plating film is made of Ni.

43. The resistor of claim **32**, wherein the second electrical insulator is made of an epoxy-based material.

44. The resistor of claim **32**, wherein the resistor element is made of one of manganin, zeranin, Ni—Cr alloy, Cu—Ni alloy, and Fe—Cr alloy.

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